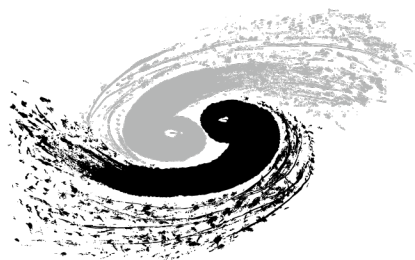


Transition-Edge Sensor Development and Application

Daikang Yan

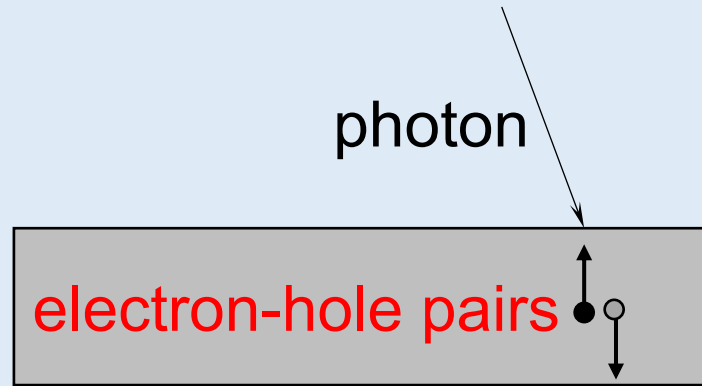
2023-10



中國科學院高能物理研究所

Institute of High Energy Physics, Chinese Academy of Sciences

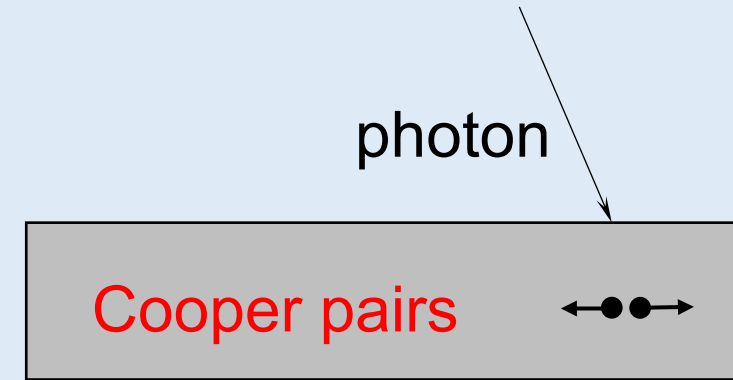
Semiconductor detector



e-h pair: ~ eV

V.S.

Superconductor detector

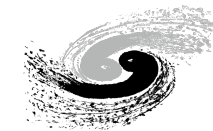


Cooper pair: ~ meV

$$\text{Poisson noise} = 1/\sqrt{N}$$

The intrinsic noise level of superconductor detectors is $1/\sqrt{1000}$ times lower
→ energy resolution 30 times better

Superconductor Detectors



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

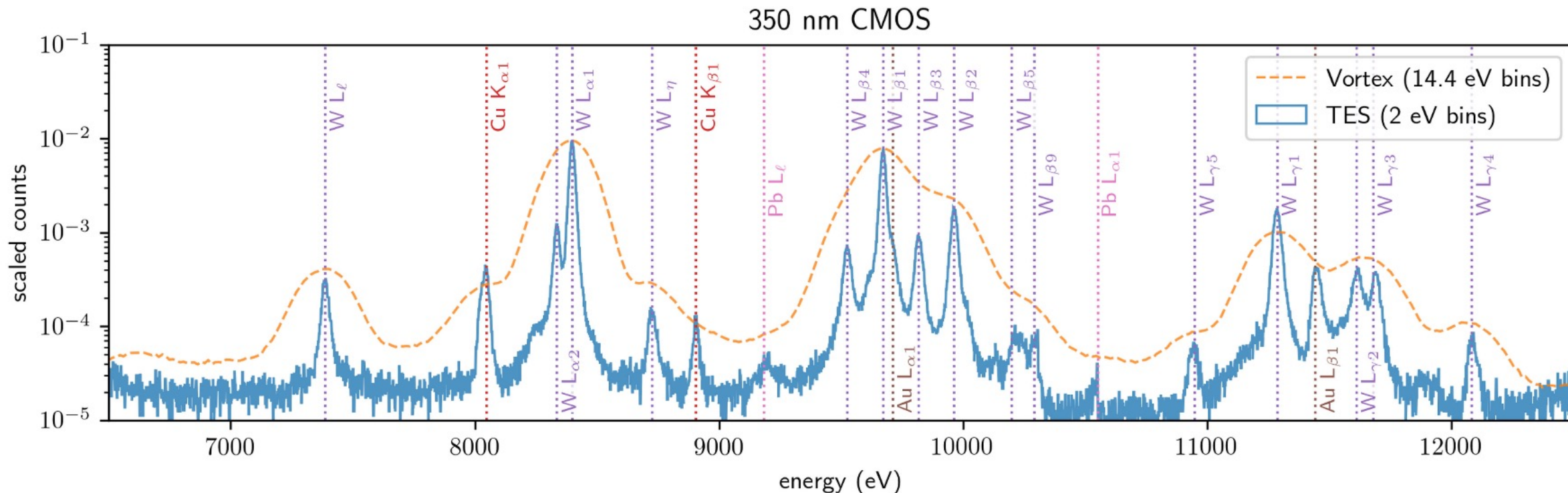


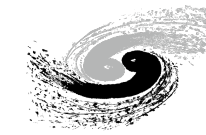
Fig. 3. Fluorescence spectra of a 350 nm CMOS integrated circuit chip, measured with a TES sensor (blue solid line) and a Vortex silicon-drift detector (orange dashed line). Prominent peaks are labeled with their corresponding element and line name.

Tejas Guruswamy et al. (2021)

Vortex (Si detector) $\Delta E = 130 \text{ eV}$

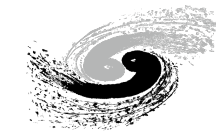
TES (Superconductor detector) $\Delta E = 12 \sim 15 \text{ eV}$

Superconductor Detectors

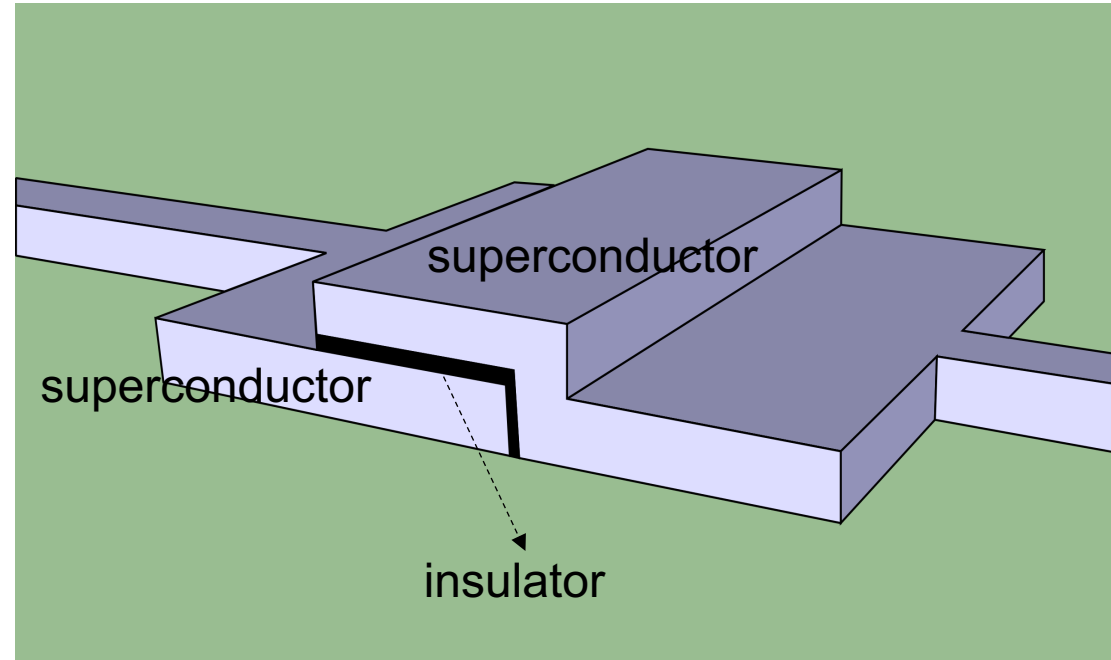


	Superconducting Tunnel Junction (STJ)	Microwave Kinetic Inductance Detectors (MKID)	Metallic Magnetic Calorimeter (MMC)	Transition-Edge Sensor (TES)
mechanism	tunnelling current proportional to number of quasiparticles	quasiparticle density influences the resonant frequency of LC circuit	magnetic flux change in the paramagnetic material	resistance change due to photon heating
ΔE (soft X-ray)	~ 10 eV	\sim several 10 eV	~ 1 eV	~ 1 eV
ΔE (hard X-ray)	detector material too thin, low absorption	rarely developed	40 eV@60 keV (can be better)	5 eV @ 17 keV
advantage	high count rate (10^4 /s)	large array multiplexing	high energy resolution; large energy range	high energy resolution; well-developed multiplex technique
disadvantage	“low” energy resolution; small energy range	“low” energy resolution; small energy range	hard to multiplex	energy range smaller than MMC

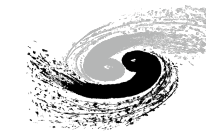
Superconductor Detectors



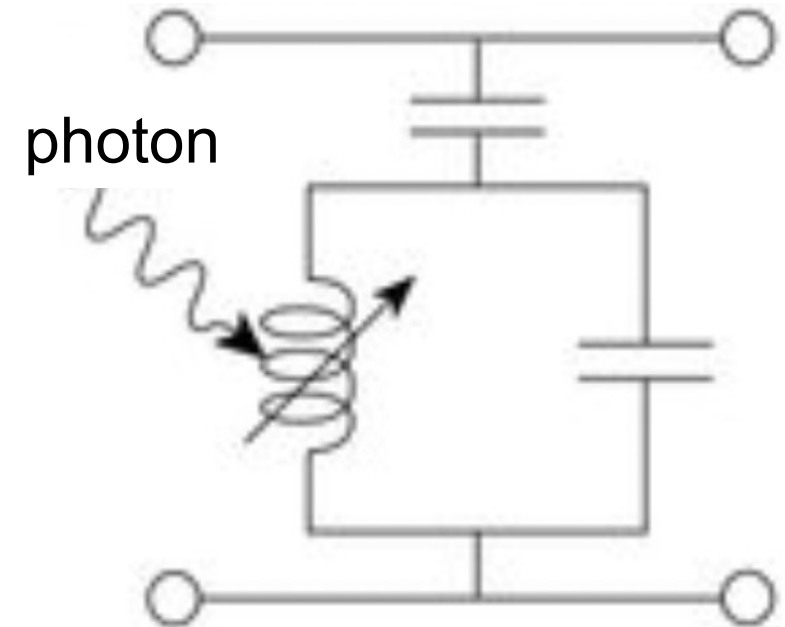
	Superconducting Tunnel Junction (STJ)
mechanism	tunnelling current proportional to number of quasiparticles
ΔE (soft X-ray)	~ 10 eV
ΔE (hard X-ray)	detector material too thin, low absorption
advantage	high count rate (10^4 /s)
disadvantage	“low” energy resolution; small energy range



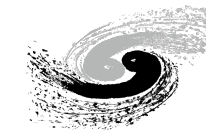
Superconductor Detectors



	Microwave Kinetic Inductance Detectors (MKID)
mechanism	quasiparticle density influences the resonant frequency of LC circuit
ΔE (soft X-ray)	~ several 10 eV
ΔE (hard X-ray)	rarely developed
advantage	large array multiplexing
disadvantage	“low” energy resolution; small energy range



Superconductor Detectors



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

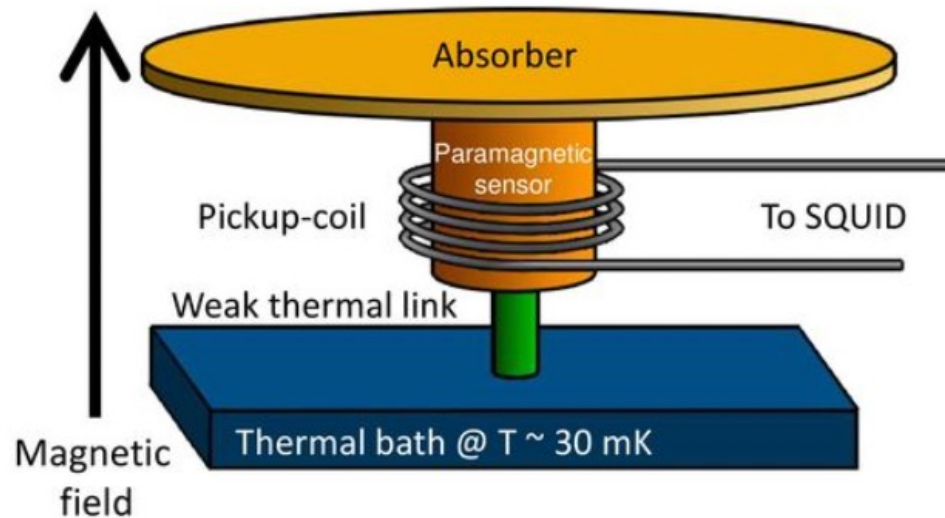
mechanism

ΔE
(soft X-ray)

ΔE
(hard X-ray)

advantage

disadvantage



Metallic Magnetic
Calorimeter
(MMC)

magnetic flux change
in the paramagnetic
material

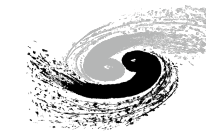
~ 1 eV

40 eV@60 keV
(can be better)

high energy
resolution;
large energy range

hard to multiplex

Superconductor Detectors



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

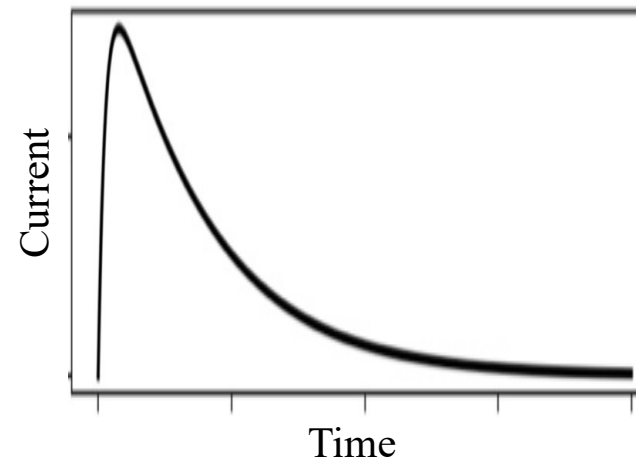
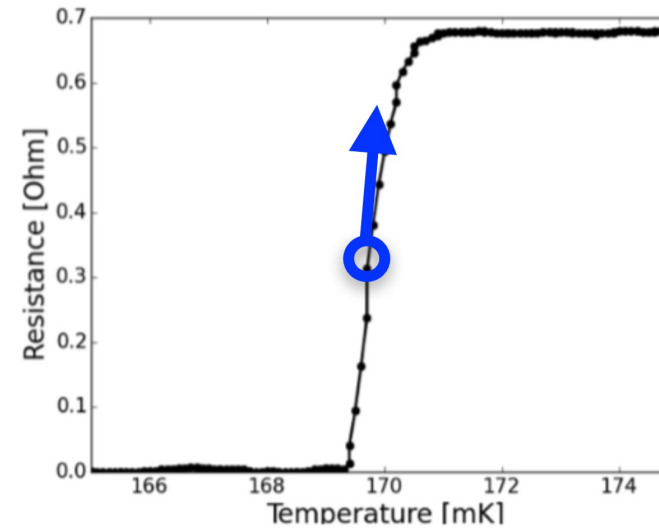
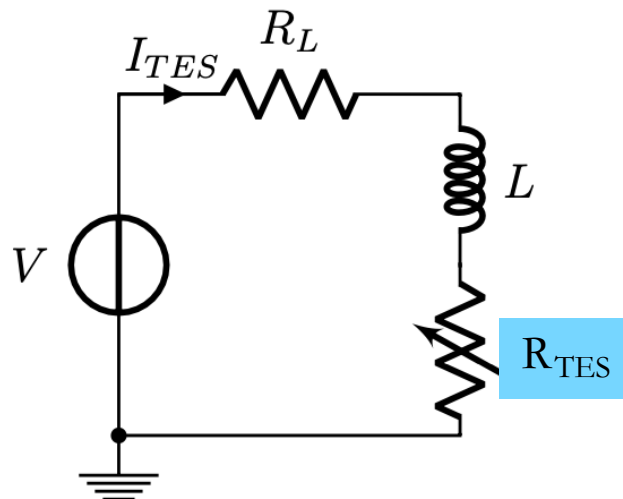
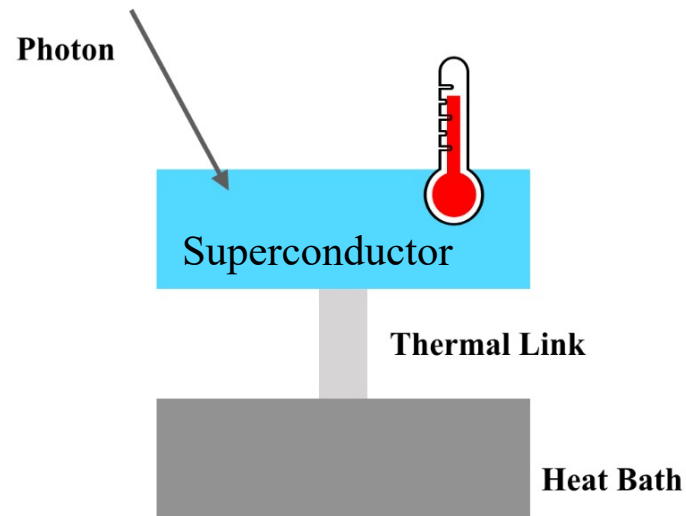
mechanism

ΔE
(soft X-ray)

ΔE
(hard X-ray)

advantage

disadvantage



Transition-Edge Sensor
(TES)

resistance change due
to photon heating

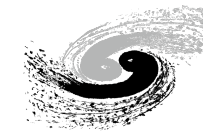
~ 1 eV

5 eV @ 17 keV

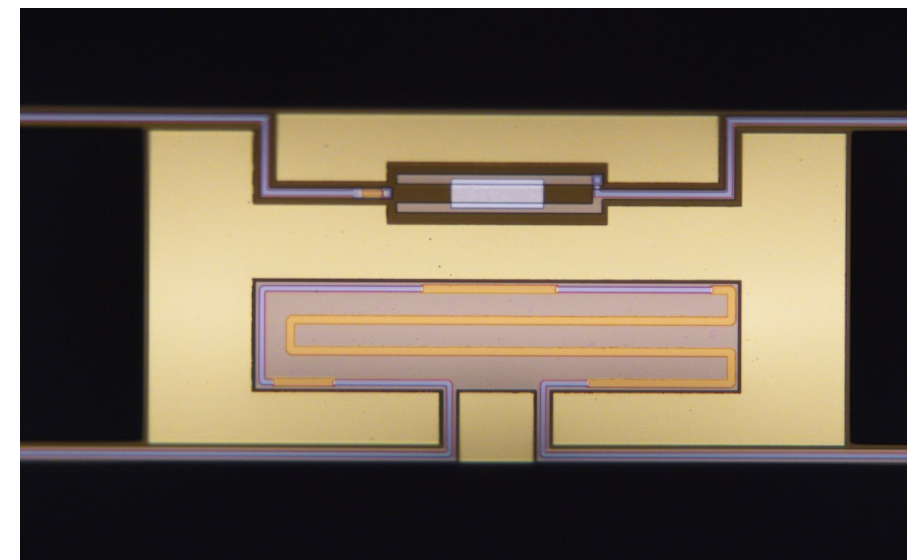
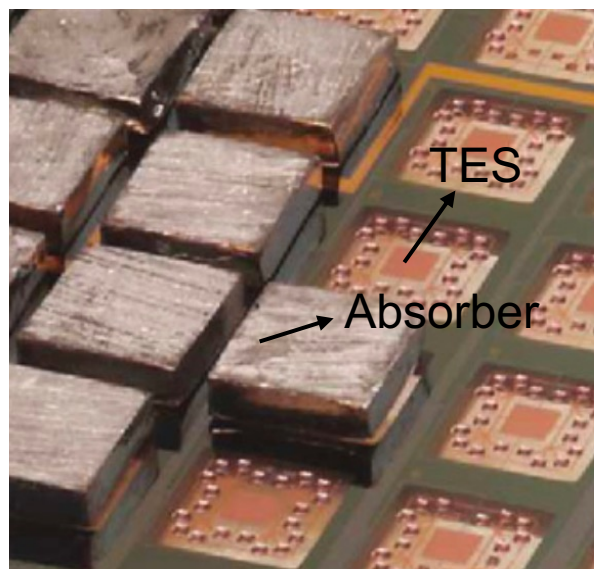
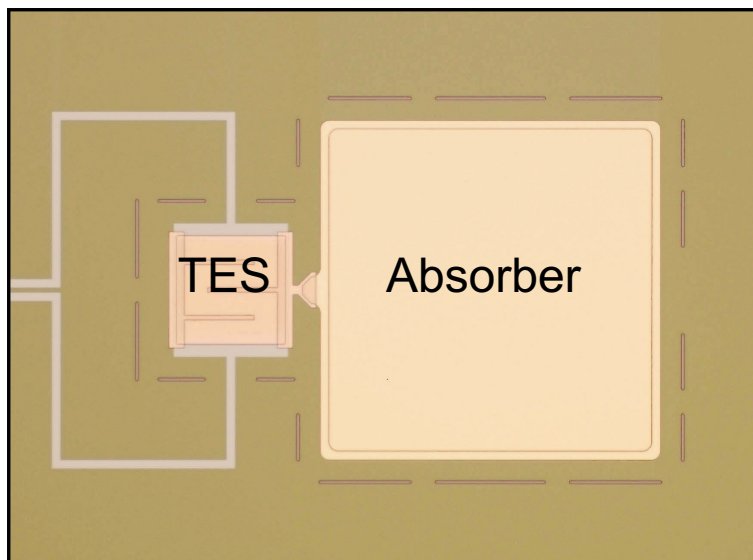
high energy resolution;
well-developed multiplex
technique

energy range smaller
than MMC

TES: Transition-Edge Sensor

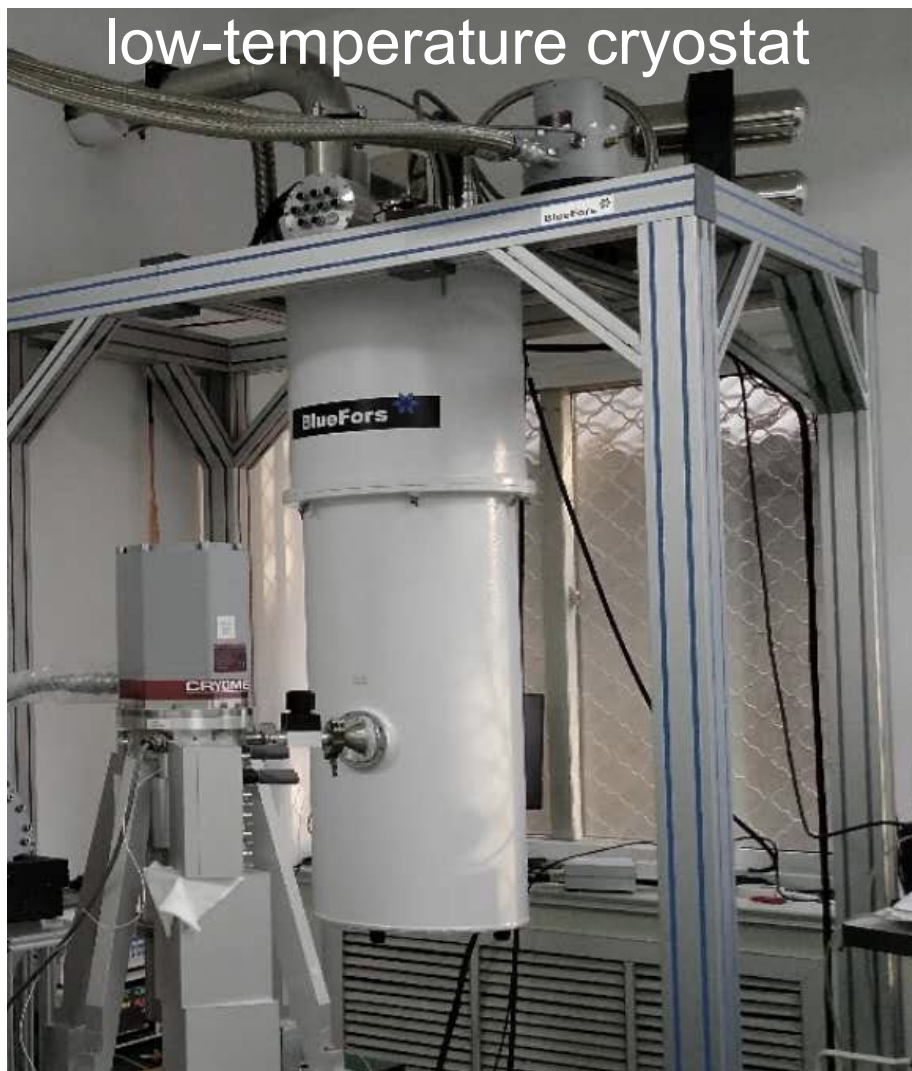


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

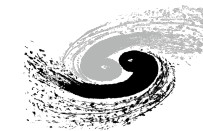


Bennett *et al.* Rev. Sci. Instrum. **83**, 093113 (2012)

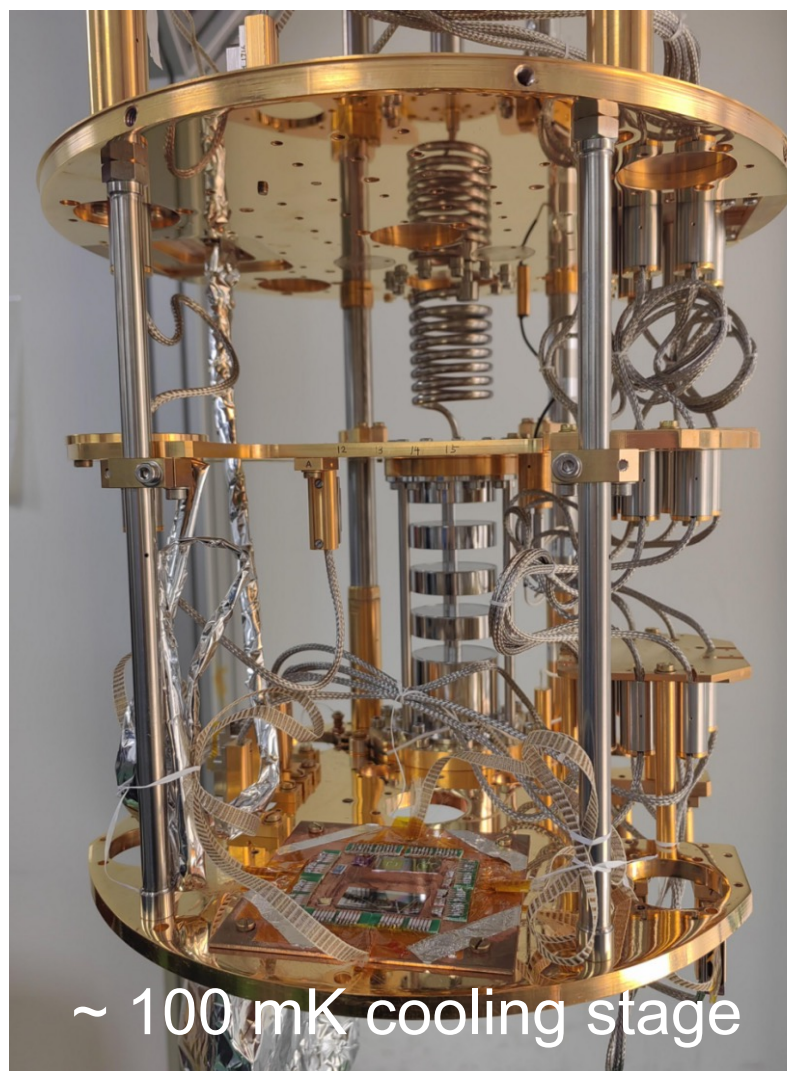
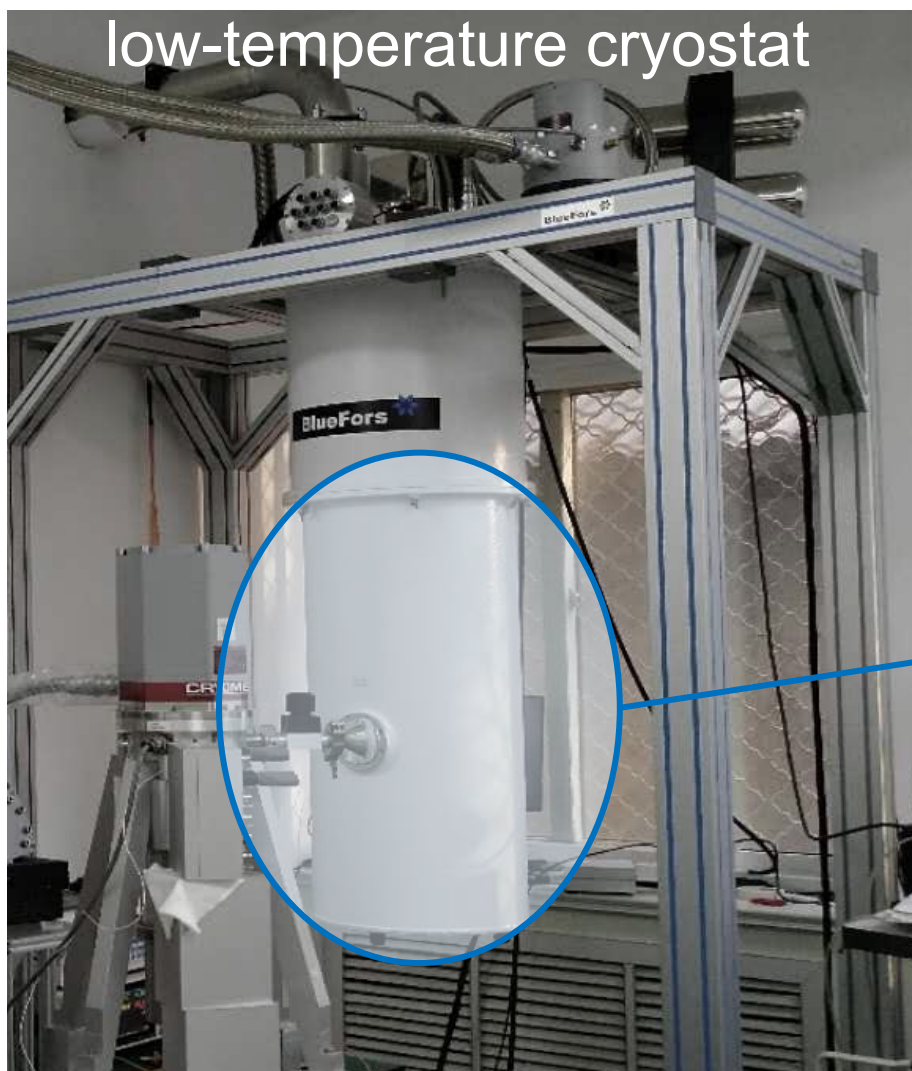
TES: Transition-Edge Sensor



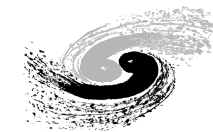
TES: Transition-Edge Sensor



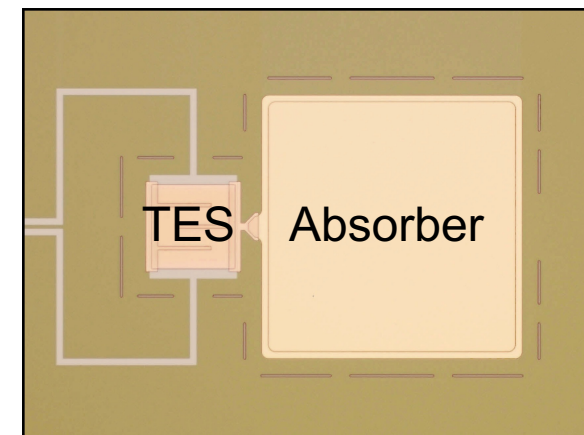
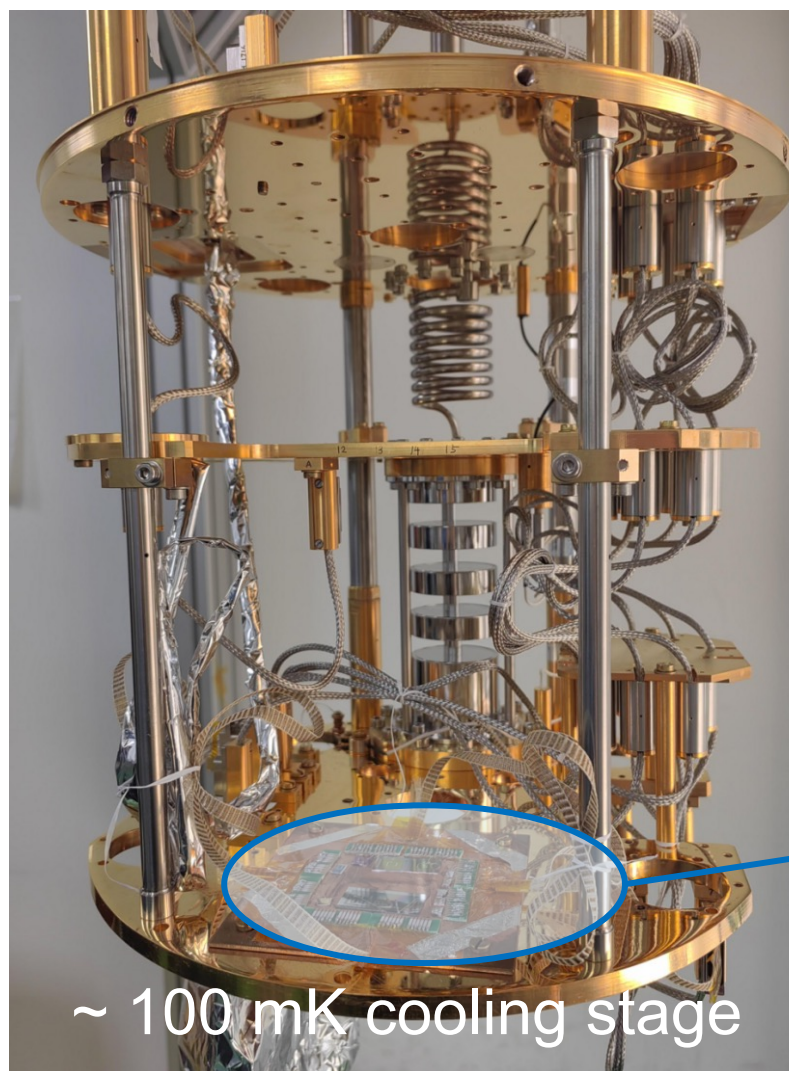
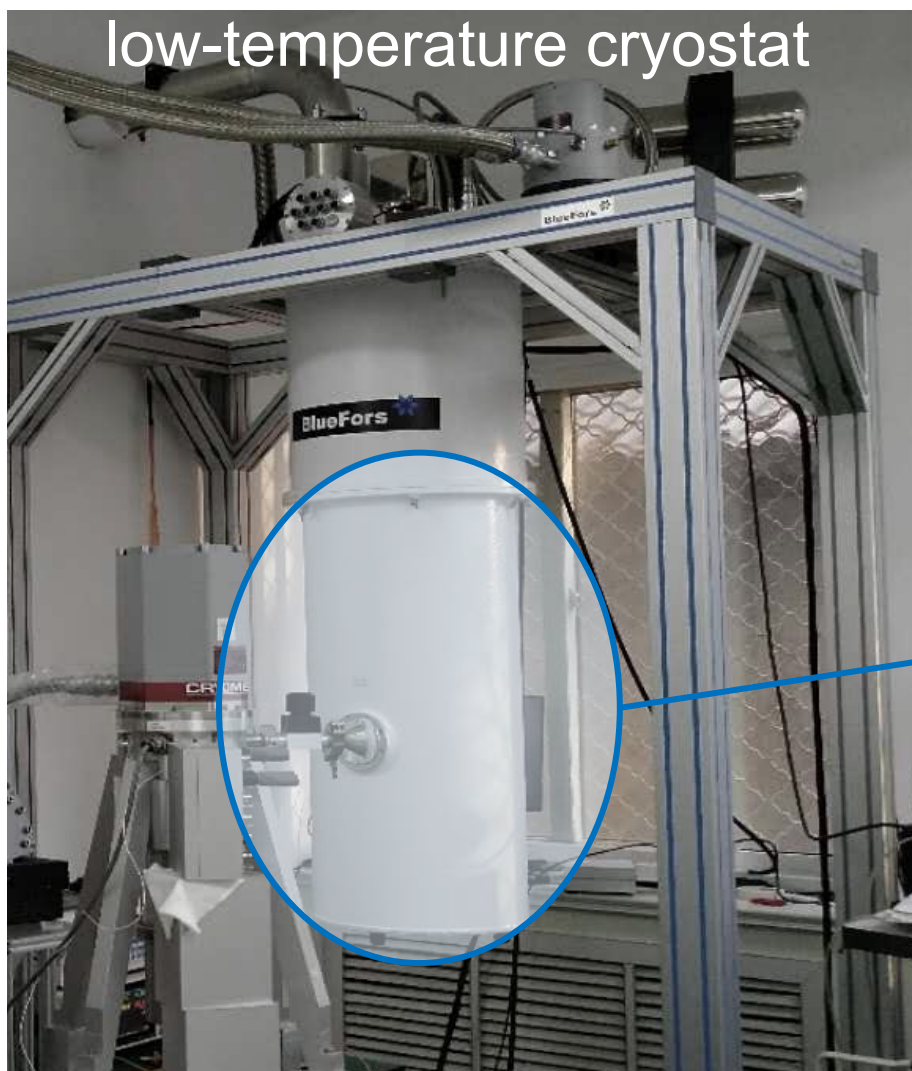
中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



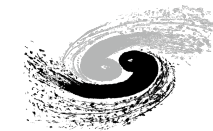
TES: Transition-Edge Sensor



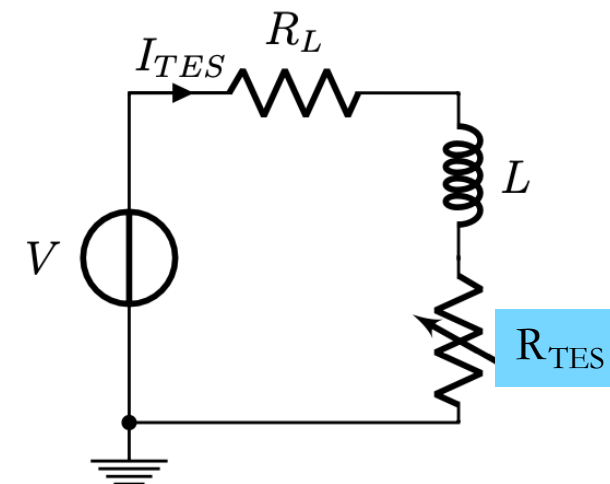
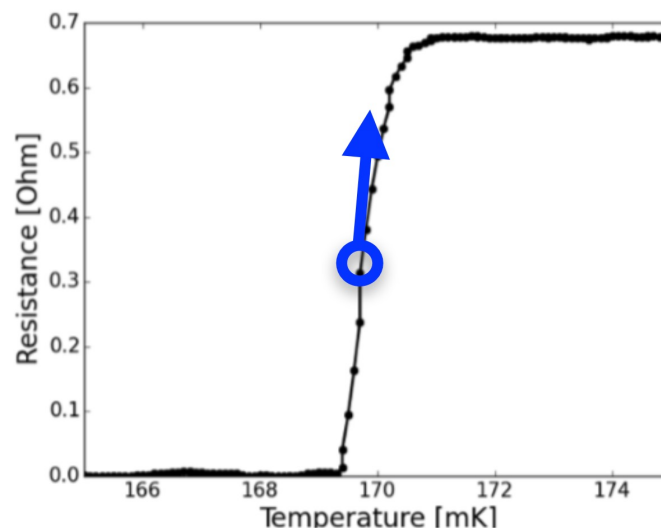
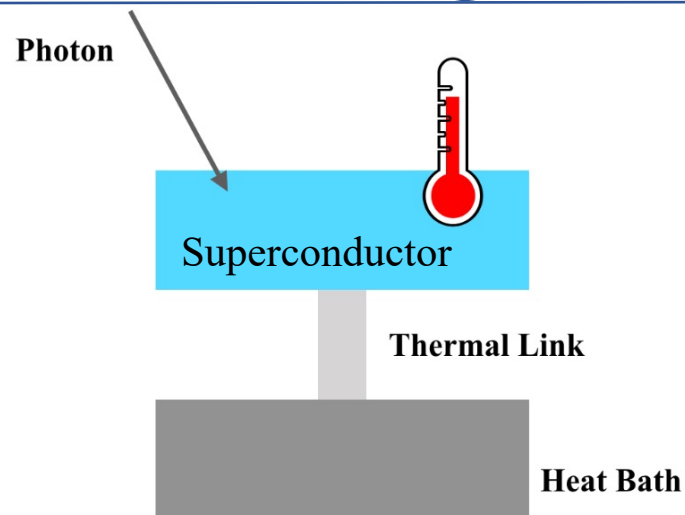
中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



TES Design



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



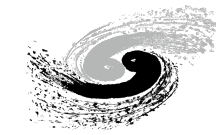
Thermal bias \leftarrow $R(T, I)$ relation \rightarrow Electrical bias

$$\frac{d\delta T}{dt} = \frac{I_0 R_0 (2 + \beta_I)}{C} \delta I - \frac{(1 - \mathcal{L}_I)}{\tau} \delta T$$

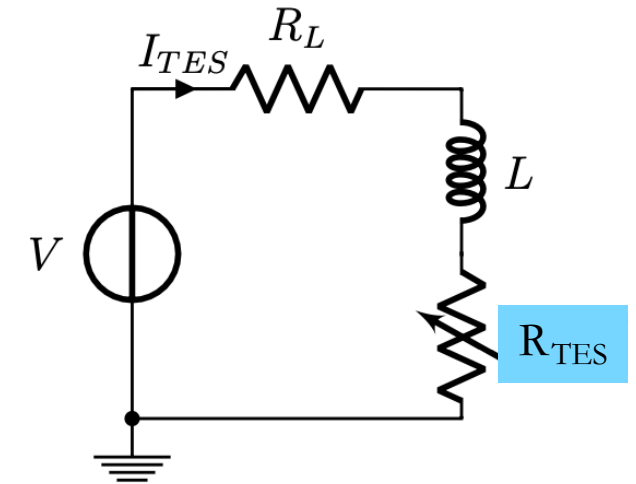
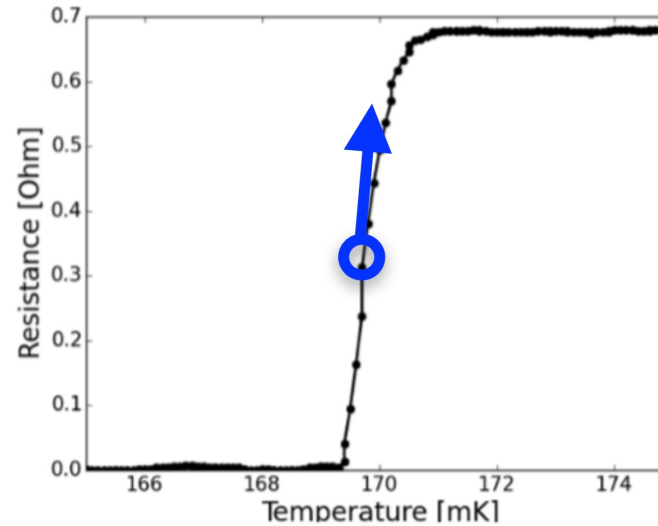
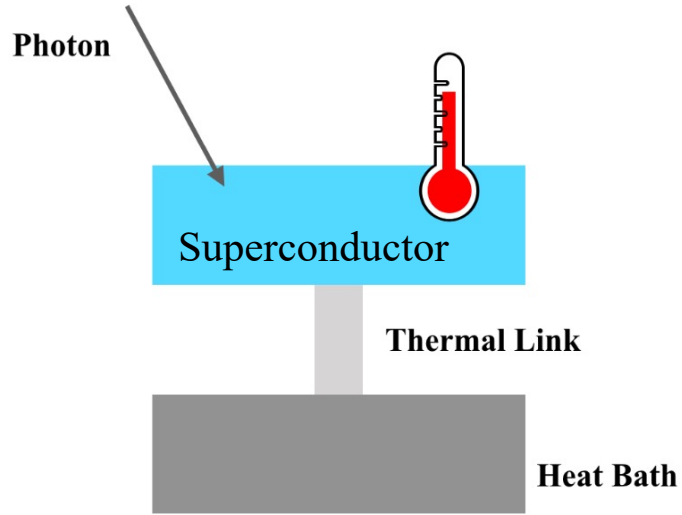
$$R(T, I) \approx R_0 + \alpha_I \frac{R_0}{T_0} \delta T + \beta_I \frac{R_0}{I_0} \delta I$$

$$\frac{d\delta I}{dt} = -\frac{R_L + R_0 (1 + \beta_I)}{L} \delta I - \frac{\mathcal{L}_I G}{I_0 L} \delta T$$

TES Design



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

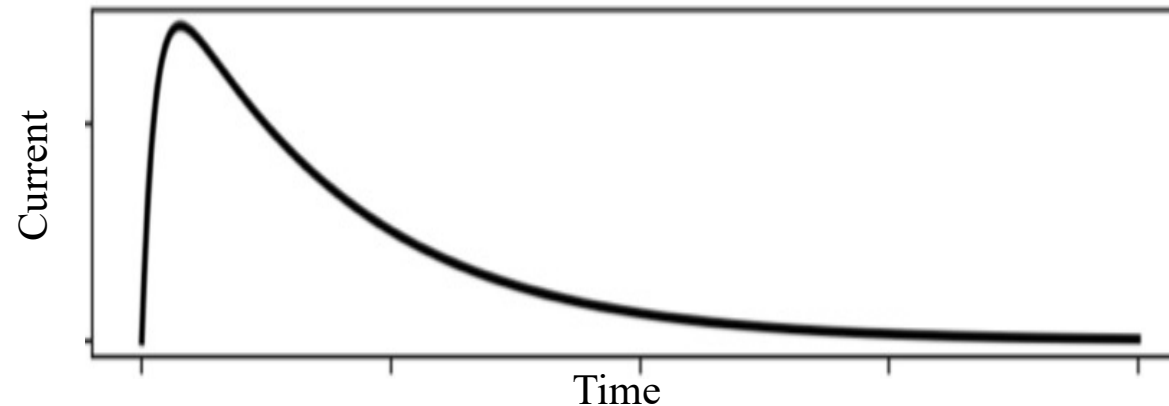


Thermal bias \leftarrow $R(T, I)$ relation \rightarrow Electrical bias

$$\frac{d\delta T}{dt} = \frac{I_0 R_0 (2 + \beta_I)}{C} \delta I - \frac{(1 - \mathcal{L}_I)}{\tau} \delta T$$

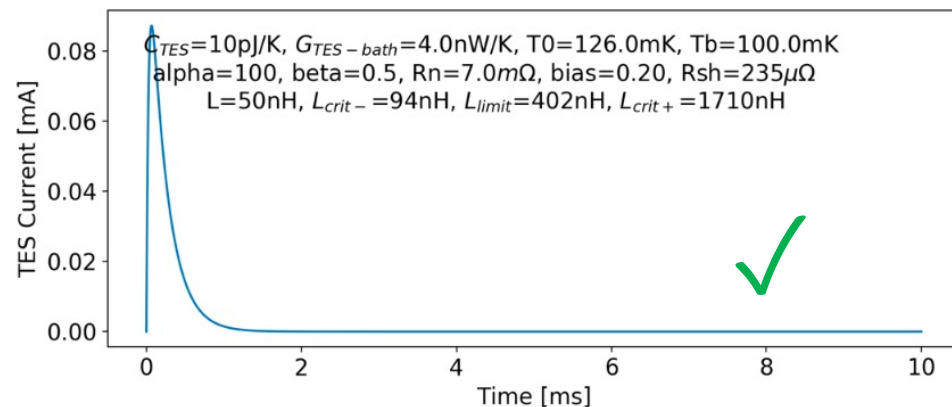
$$R(T, I) \approx R_0 + \alpha_I \frac{R_0}{T_0} \delta T + \beta_I \frac{R_0}{I_0} \delta I$$

$$\frac{d\delta I}{dt} = -\frac{R_L + R_0 (1 + \beta_I)}{L} \delta I - \frac{\mathcal{L}_I G}{I_0 L} \delta T$$

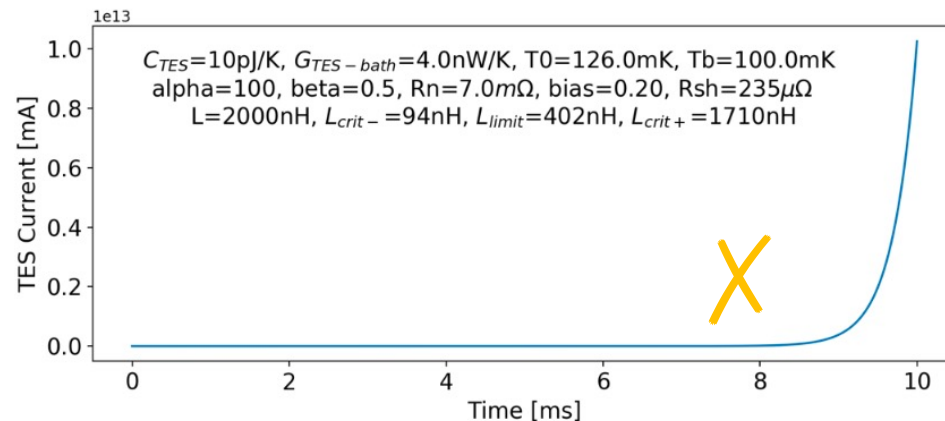


Thermal and electrical parameters should be carefully chosen to produce **stable signal response**

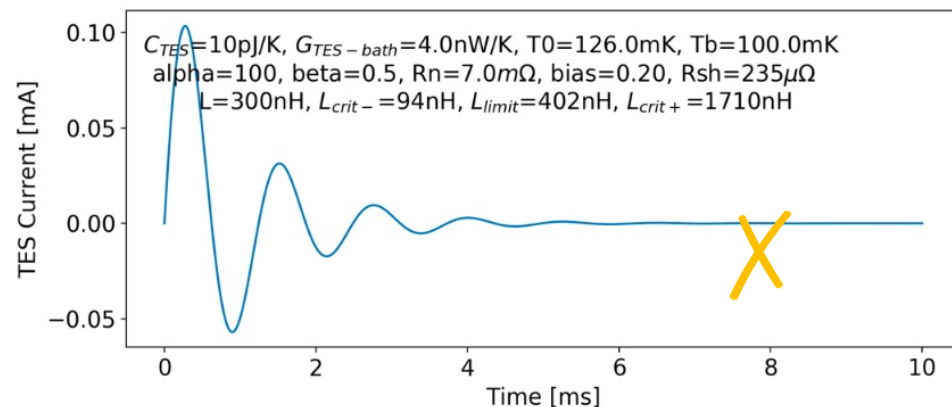
(a) $L < L_{crit-}$, overdamped, stable



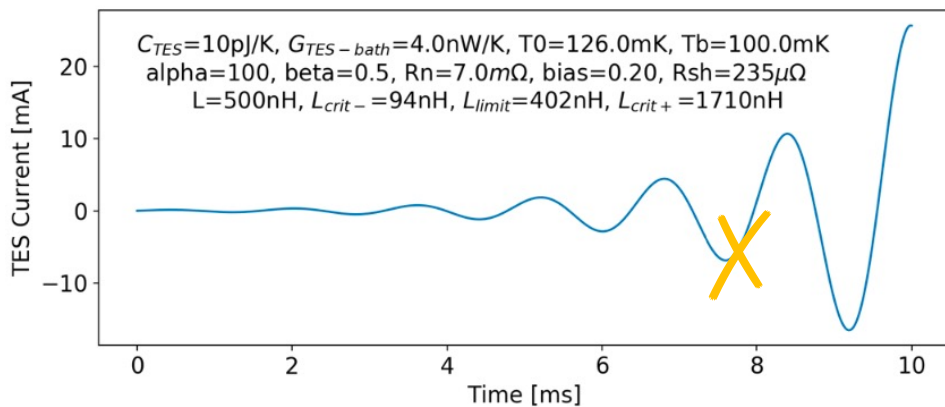
(c) $L > L_{crit+}$, overdamped, unstable

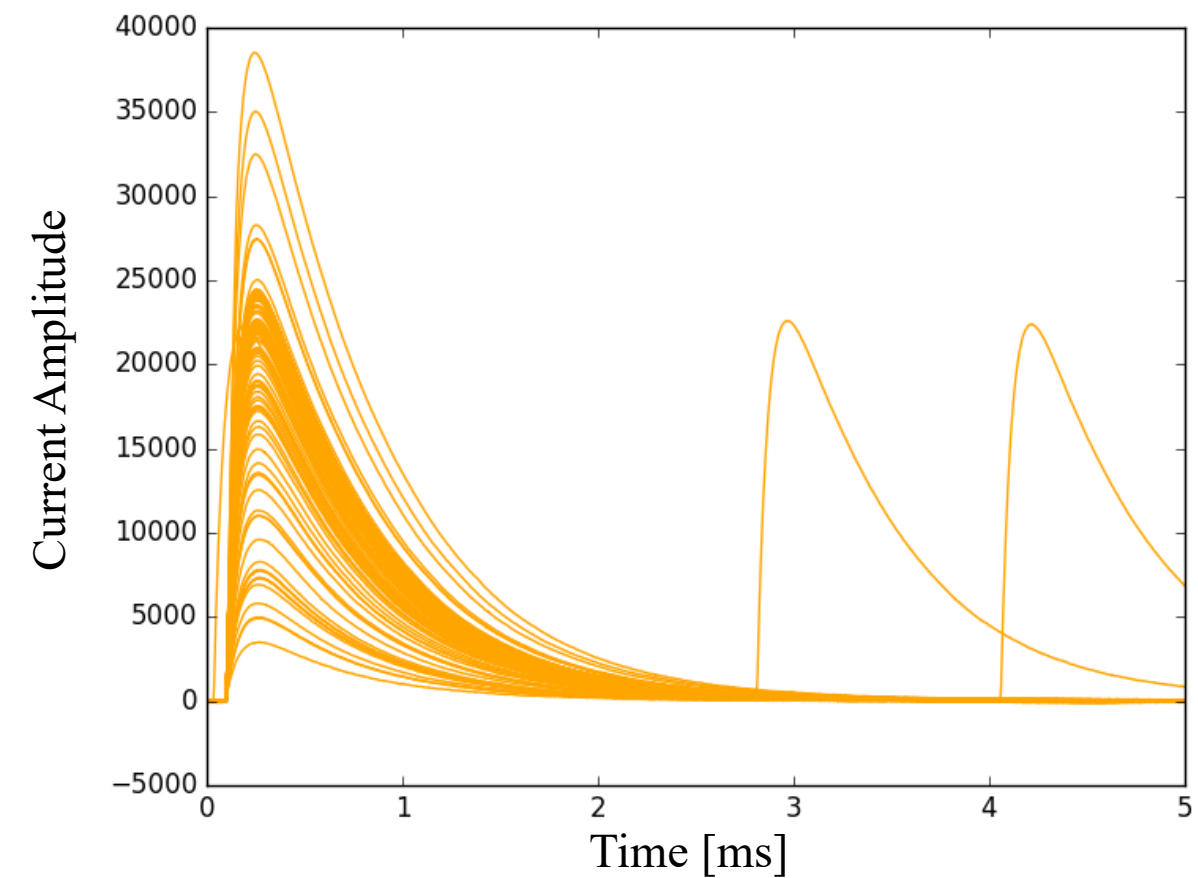
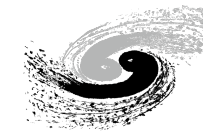


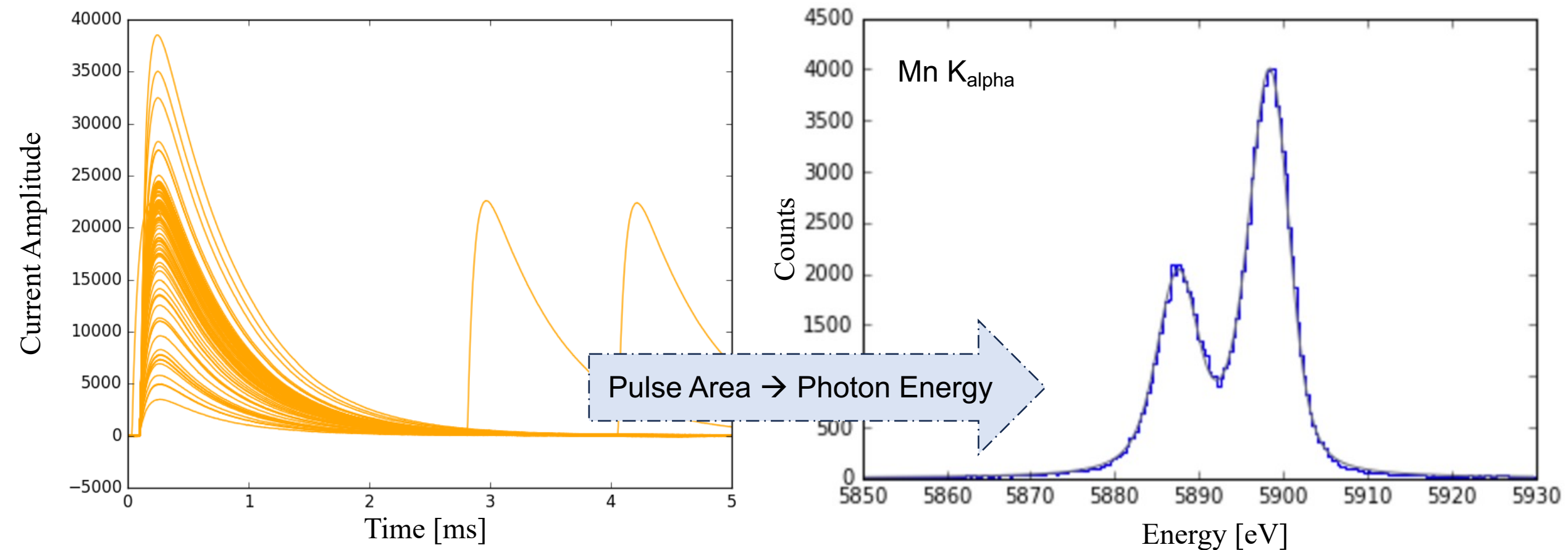
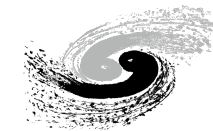
(b) $L_{crit-} < L < L_{limit}$, underdamped, stable



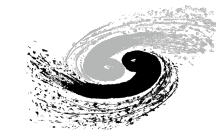
(d) $L_{limit} < L < L_{crit+}$, underdamped, unstable







Application I: X-ray Science



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

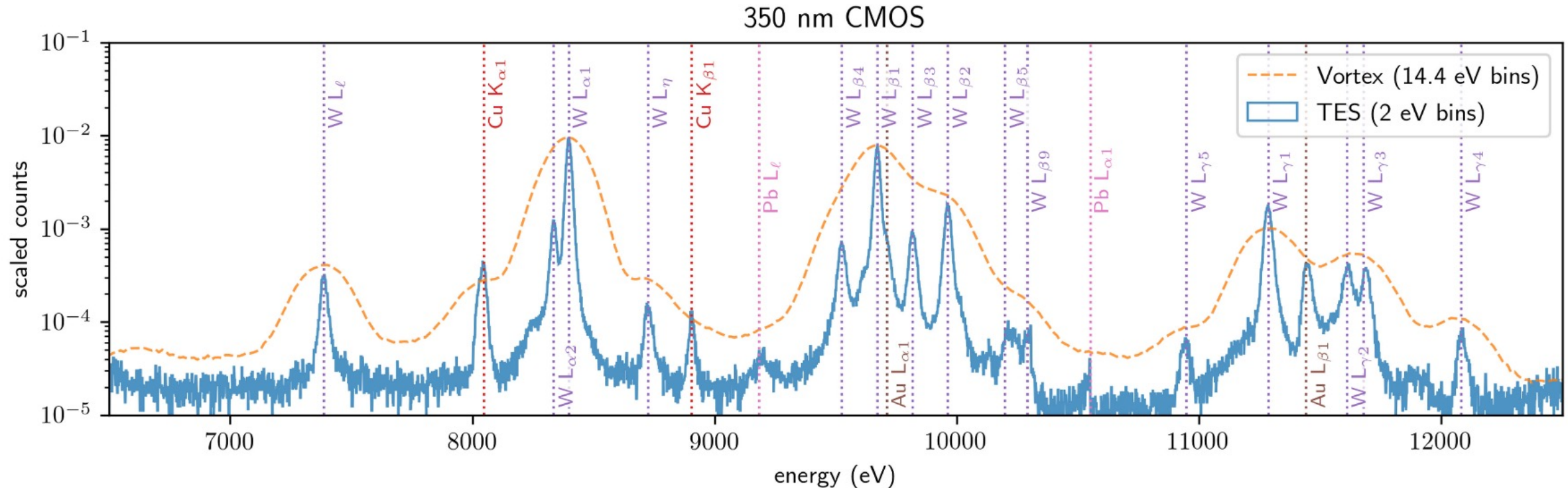
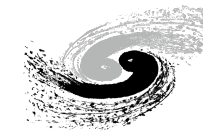


Fig. 3. Fluorescence spectra of a 350 nm CMOS integrated circuit chip, measured with a TES sensor (blue solid line) and a Vortex silicon-drift detector (orange dashed line). Prominent peaks are labeled with their corresponding element and line name.

Tejas Guruswamy et al. (2021)

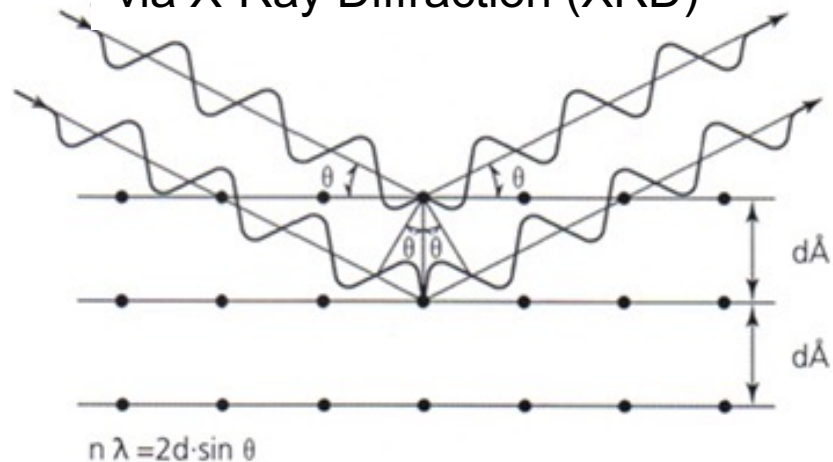
- ✓ neighboring spectral lines
- ✓ low content elements

Application I: X-ray Science

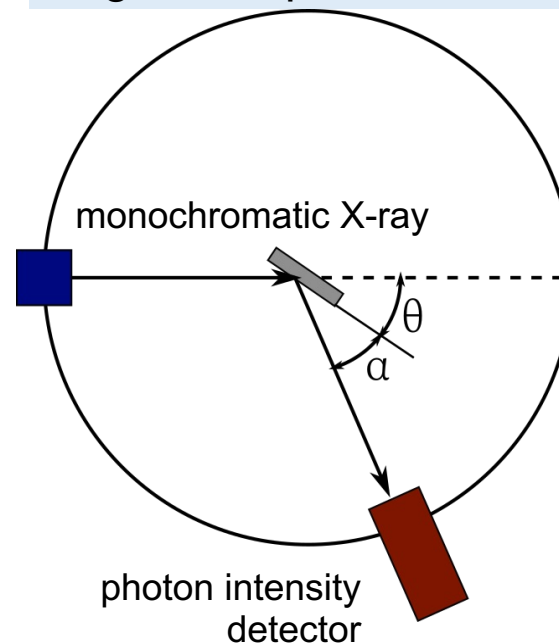


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

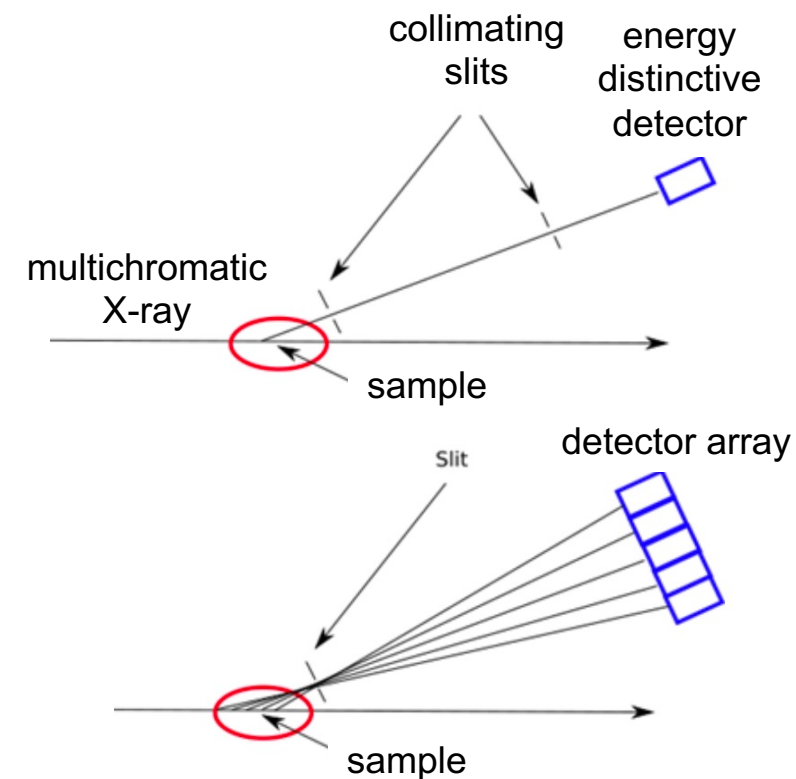
detect crystal structure
via X-Ray Diffraction (XRD)



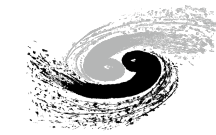
angular dispersive XRD



energy dispersive XRD

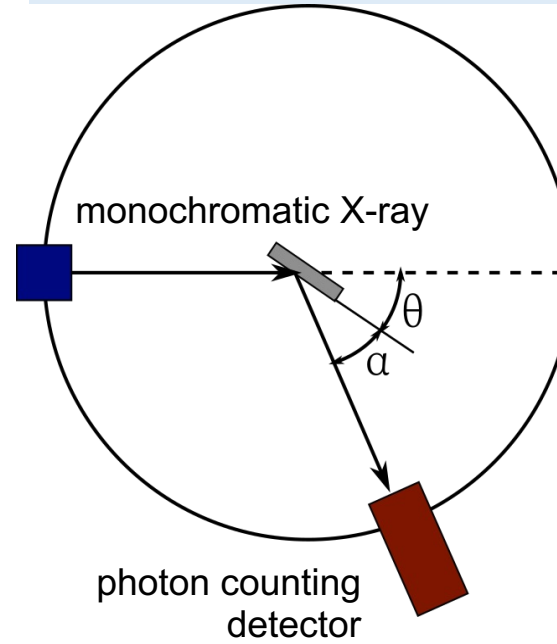


Application I: X-ray Science

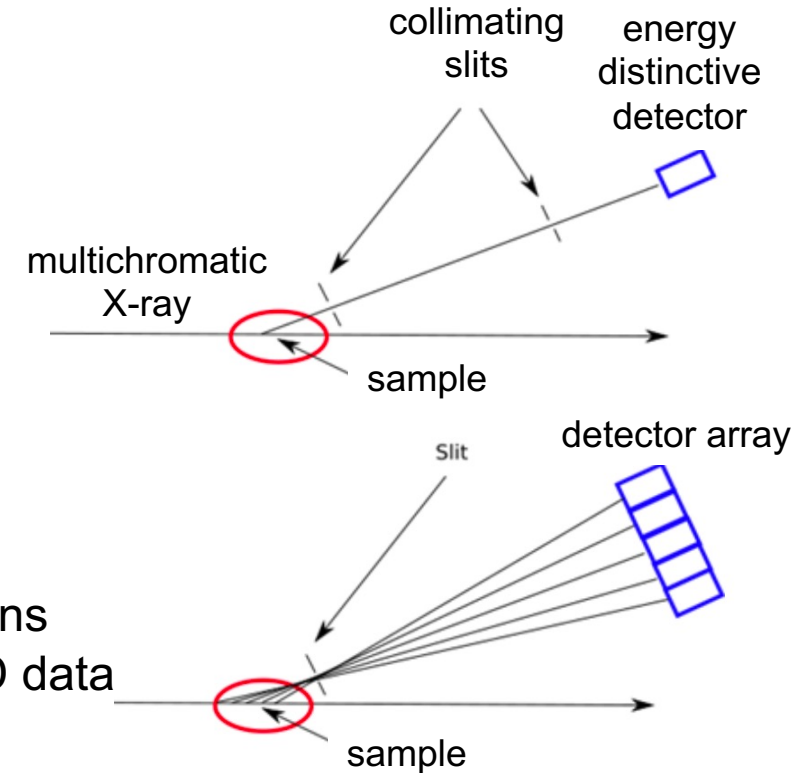


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

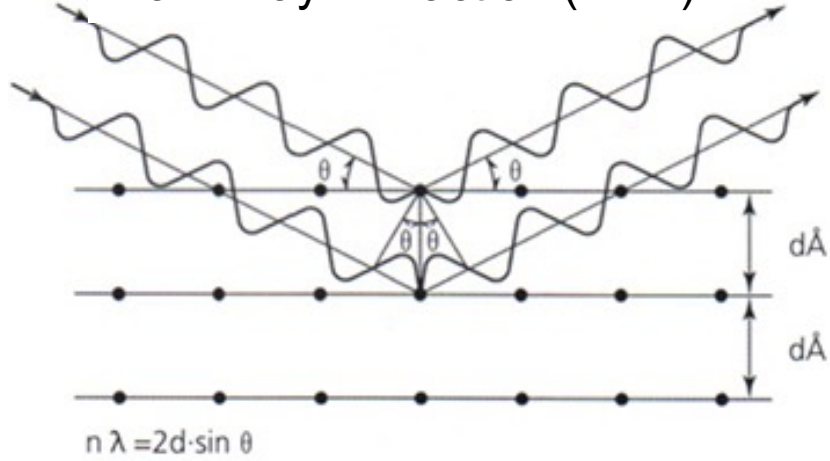
angular dispersive XRD



energy dispersive XRD



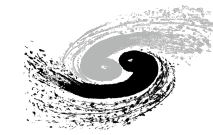
detect crystal structure
via X-Ray Diffraction (XRD)



advantage of energy dispersive XRD:

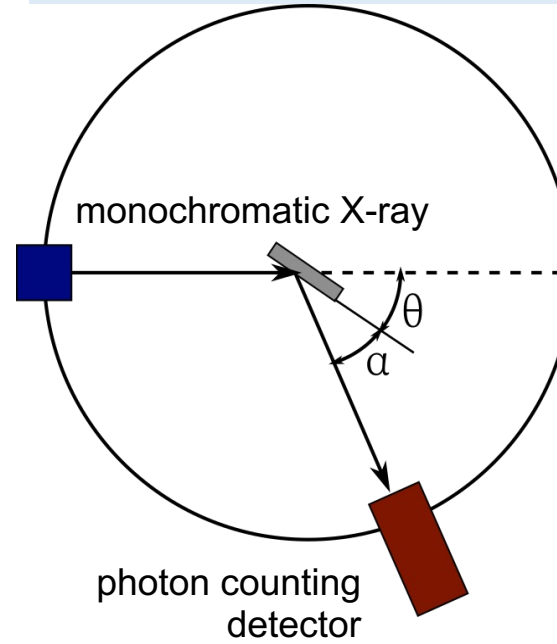
- flexibility: fixed angle, convenient for experiments with extreme conditions
- 2 function in 1 shot: measures characteristic spectra while getting XRD data
- large volume of interest

Application I: X-ray Science

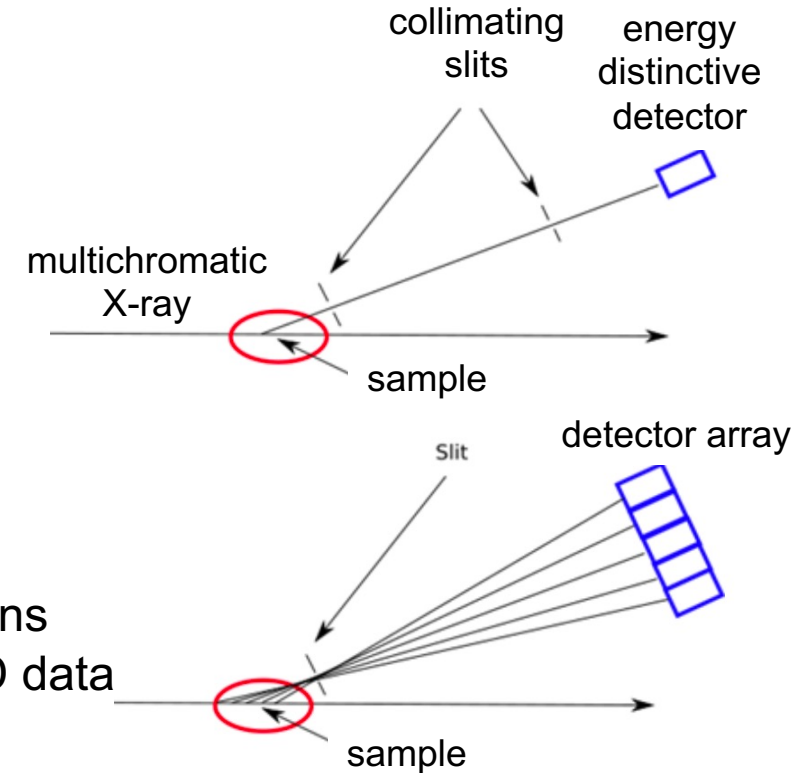


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

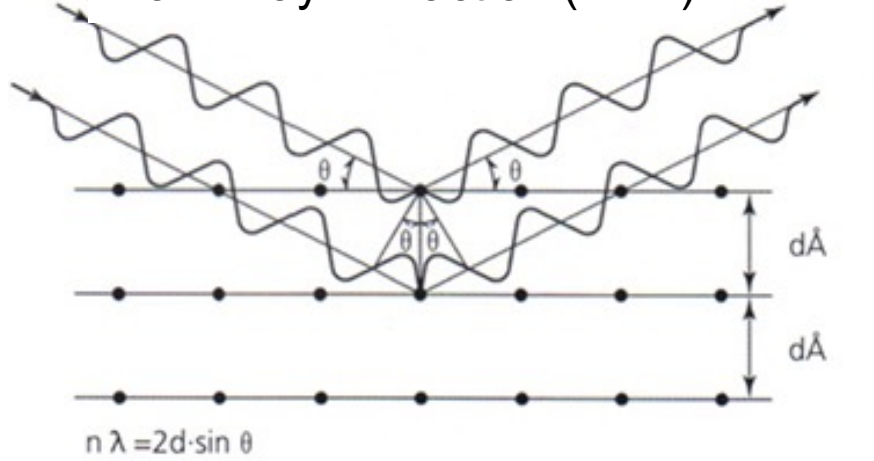
angular dispersive XRD



energy dispersive XRD



detect crystal structure
via X-Ray Diffraction (XRD)



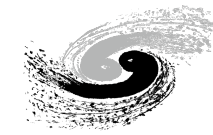
advantage of energy dispersive XRD:

- flexibility: fixed angle, convenient for experiments with extreme conditions
- 2 function in 1 shot: measures characteristic spectra while getting XRD data
- large volume of interest

disadvantage:

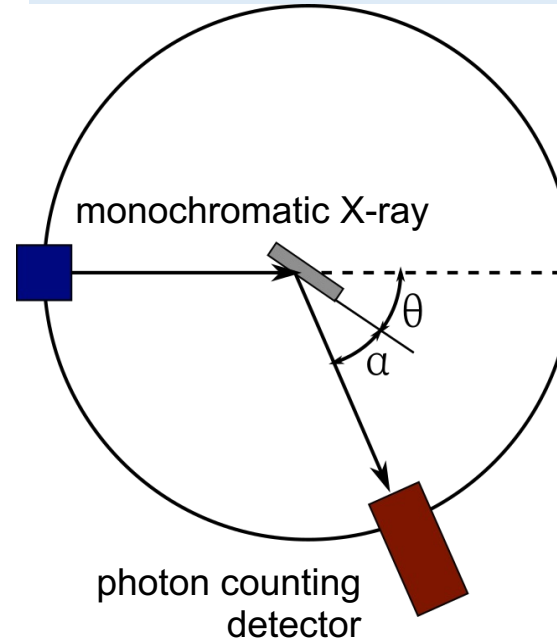
- resolution worse than angular dispersive XRD with semiconductor detectors (770 eV @ 112 keV)

Application I: X-ray Science

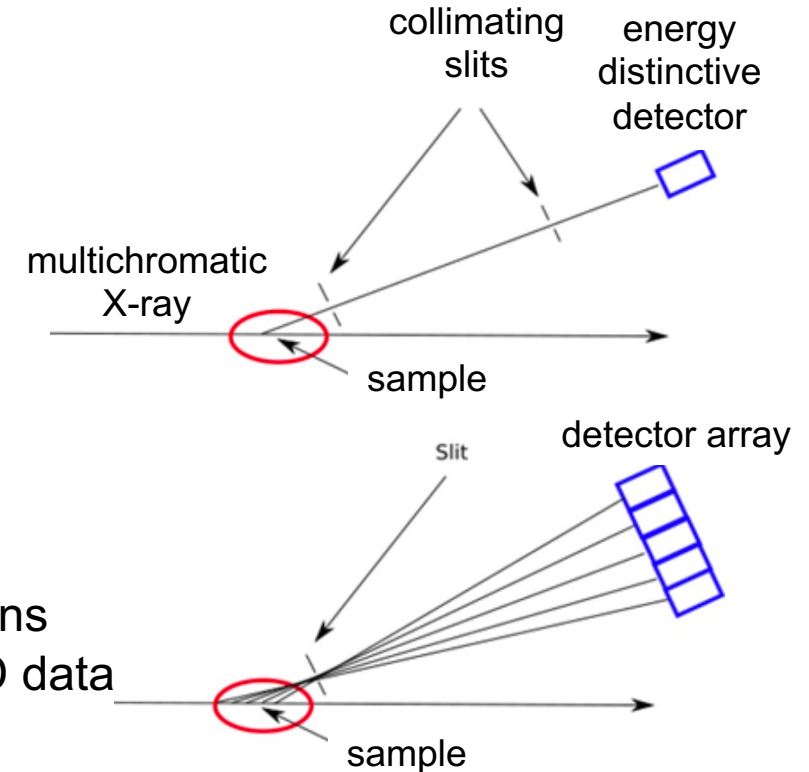


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

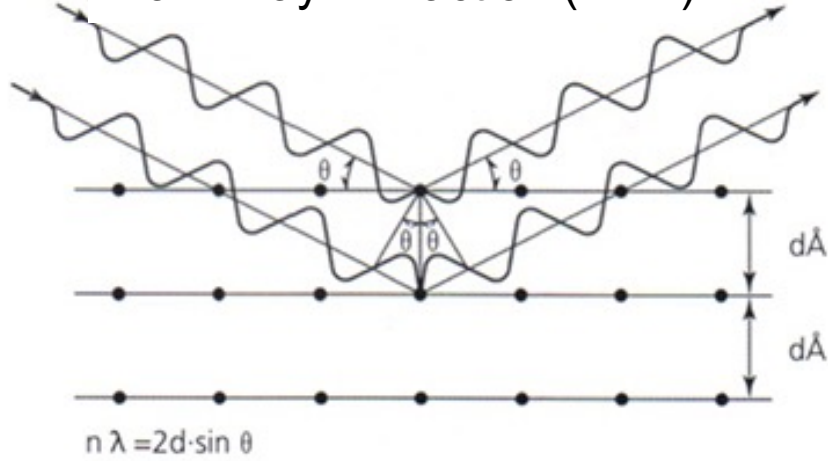
angular dispersive XRD



energy dispersive XRD



detect crystal structure
via X-Ray Diffraction (XRD)



advantage of energy dispersive XRD:

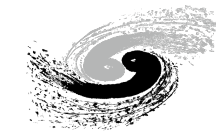
- flexibility: fixed angle, convenient for experiments with extreme conditions
- 2 function in 1 shot: measures characteristic spectra while getting XRD data
- large volume of interest

disadvantage:

- resolution worse than angular dispersive XRD with semiconductor detectors (770 eV @ 112 keV)

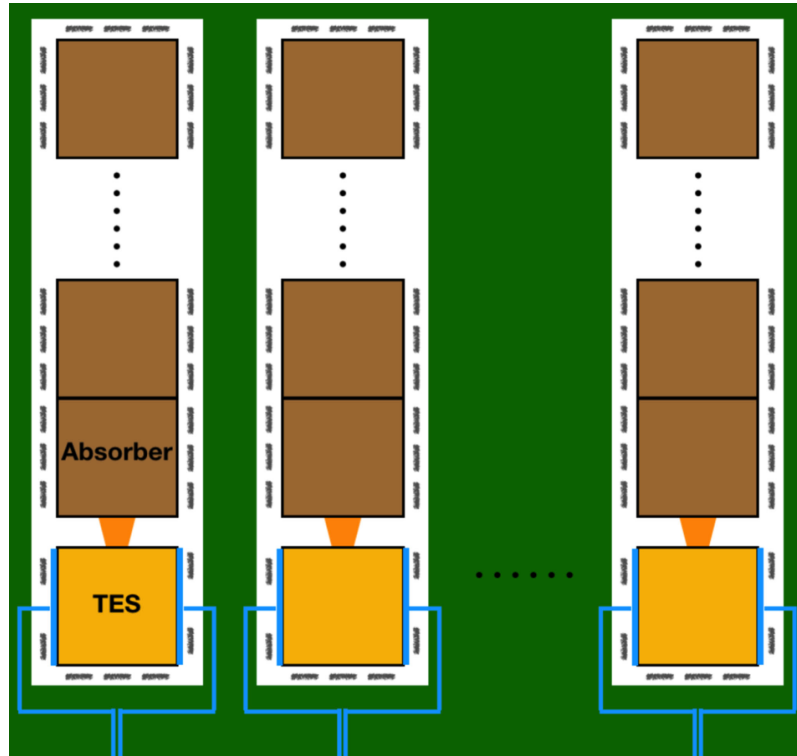
TES detector: 80 eV @ 100 keV, can compete with angular dispersive XRD

Application I: X-ray Science



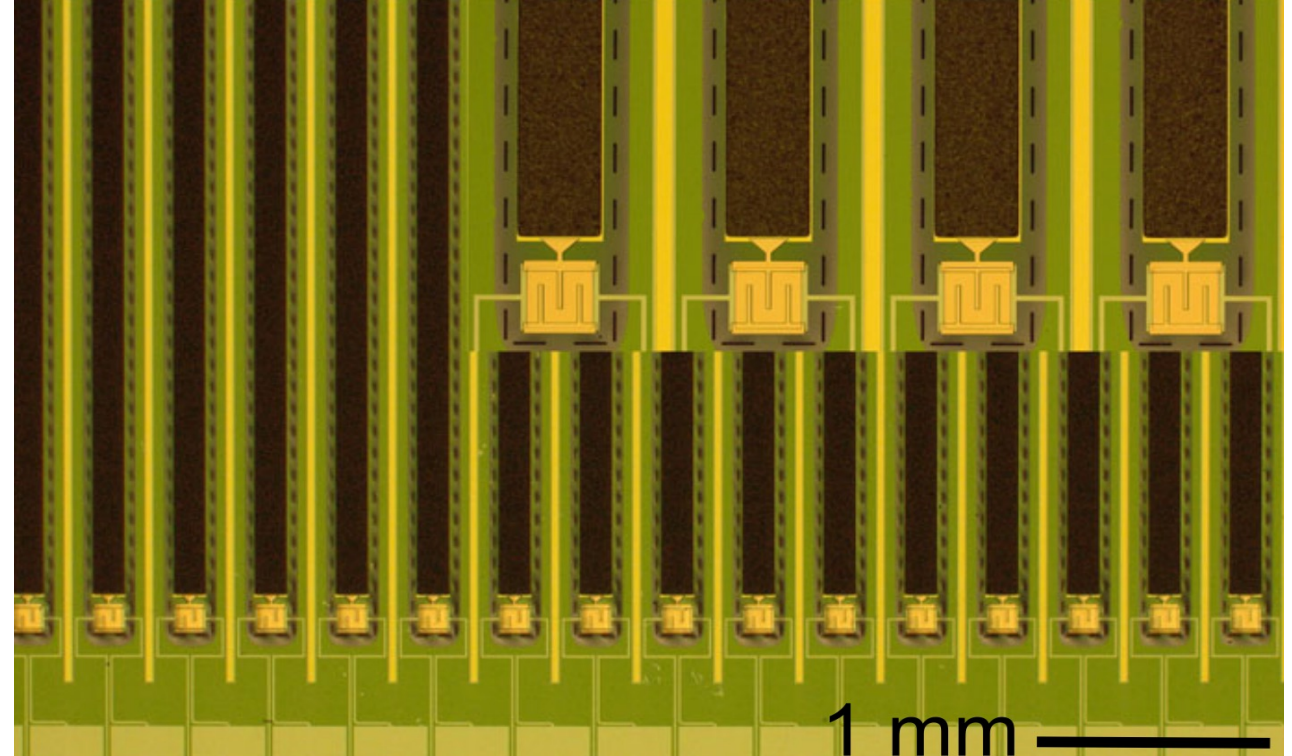
中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

design



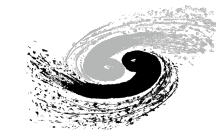
Daikang Yan *et al.* *IEEE Trans. Appl. Supercond.* 29, 1–4 (2019)

1st version of fabrication



Umeshkumar Patel ... Daikang Yan *J. of Low Temp. Phys.* 199, 384–392 (2020)

Application II: QED



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

Muon: same charge as an electron, 200 times more massive

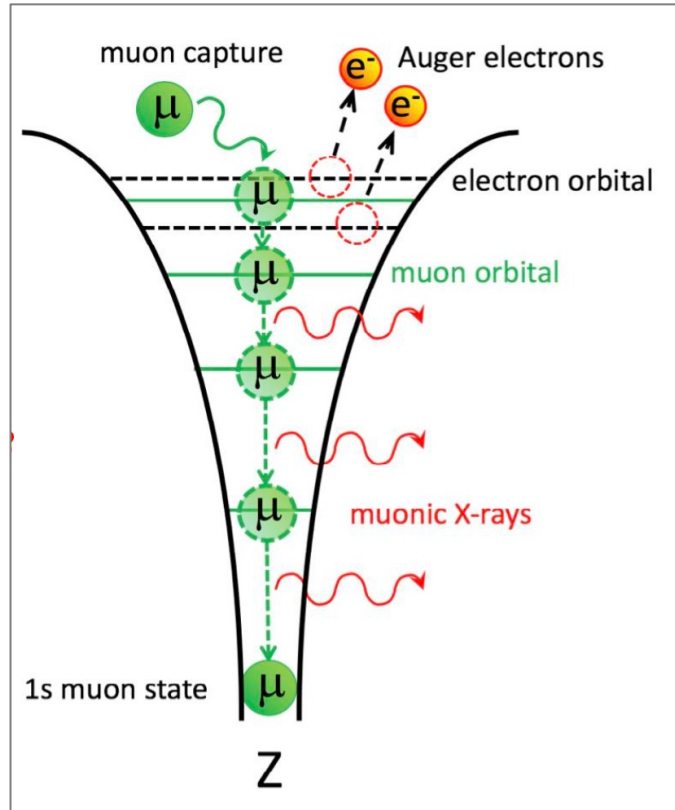


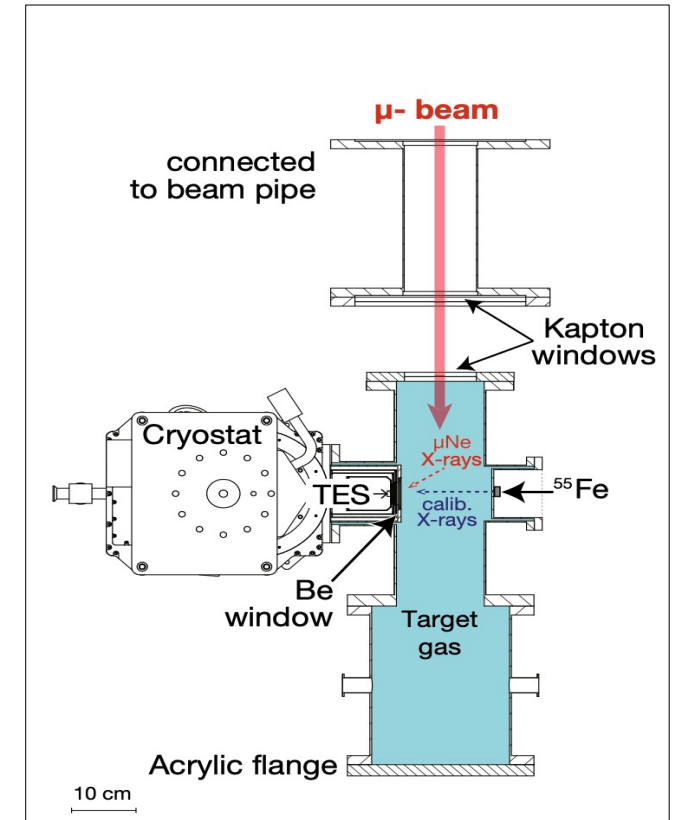
Figure credit: T. Okumura, RIKEN

Muonic atom Bohr radius: 200 times smaller

Coulomb field: 40,000 times stronger

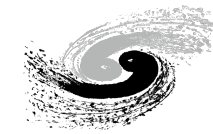
Study QED (quantum electrodynamics)
under extremely strong electric fields
by

measuring the x-ray energy of
muonic atom de-excitation



S. Okada *et al.*, Journal of Low
Temperature Physics (2020)
200:445–451

Application II: QED



Target μ -Ar energy: — 44.3 keV, predicted QED shift 99 eV
— 20.5 keV, predicted QED shift 23 eV

Measurement goal: **measure absolute energy with accuracy of ~ 1 eV**

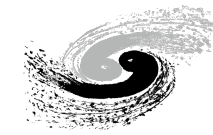


Traditional semiconductor detectors does not have enough **energy resolution** (500 eV @ 45 keV).

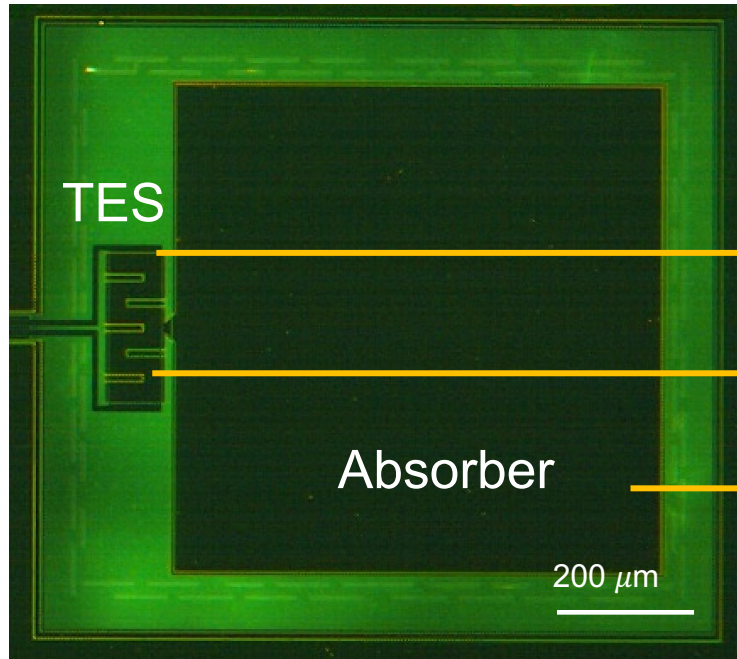
TES is a good candidate for this application, the key design considerations are:

- good linearity under 45 keV $\rightarrow E_{\text{sat}} \propto C/\alpha$
- good energy resolution $\rightarrow \Delta E \propto \sqrt{C/\alpha}$
- high collecting efficiency \rightarrow multiplexing, large absorber

Application II: QED



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



TES:
Mo/Au bilayer

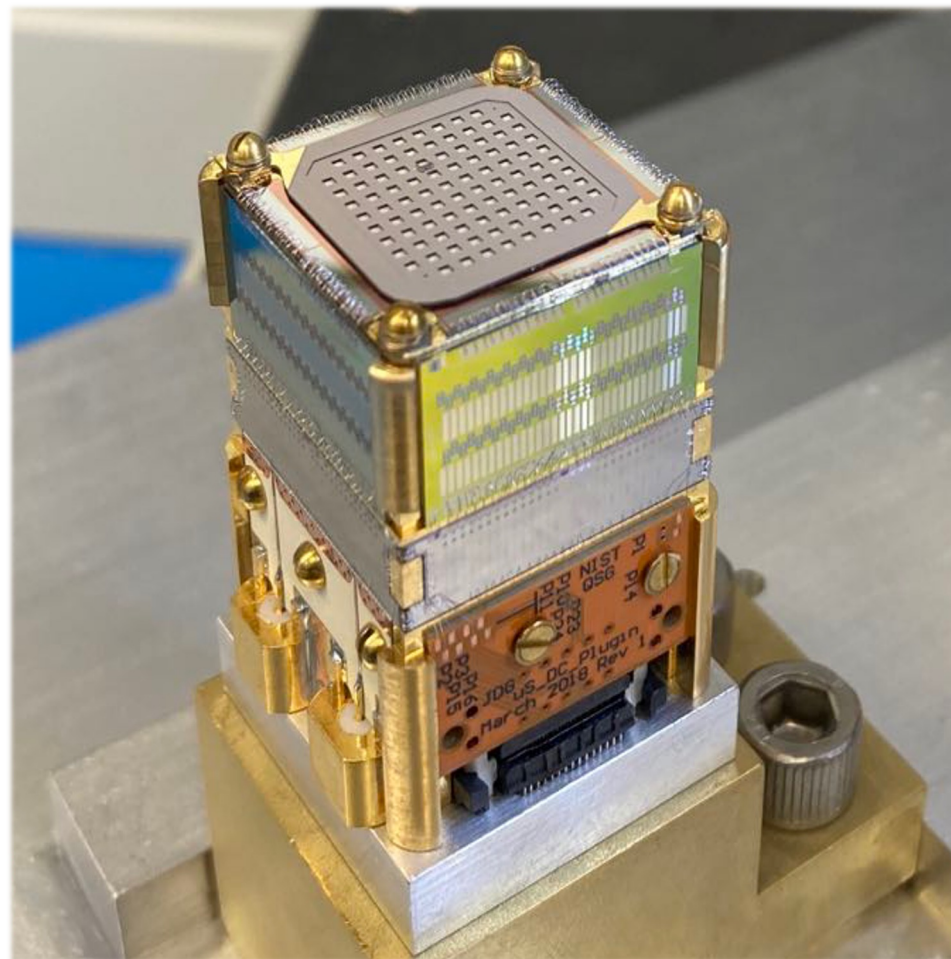
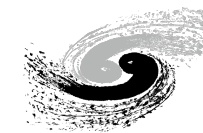
Au bars: suppress noise and adjust $\alpha = \frac{\partial \log R}{\partial \log T}$

Absorber:

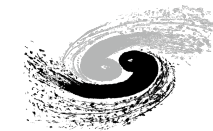
Au: large specific heat, set the total C

Bi: small specific heat, thick plating to increase QE

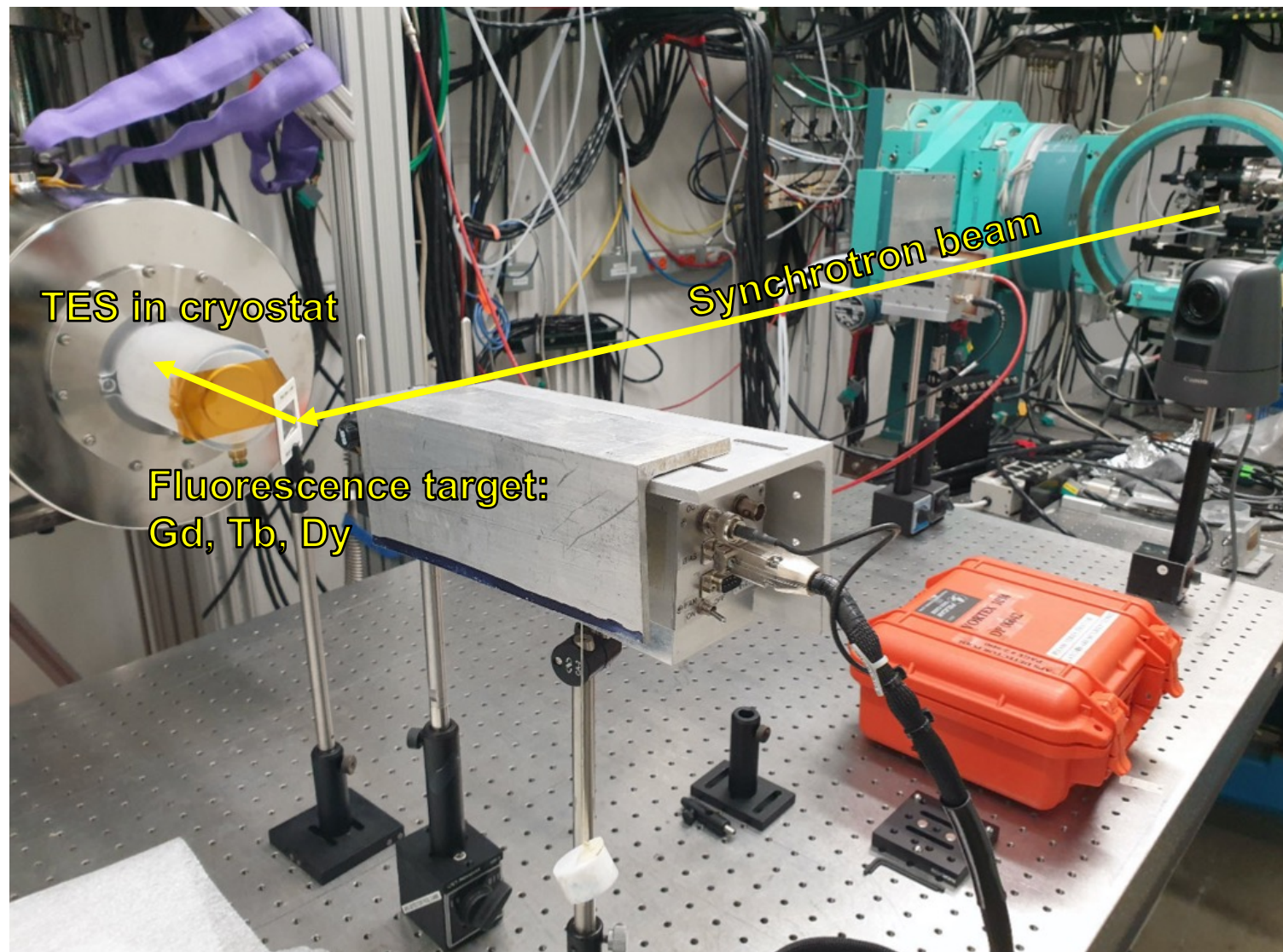
Application II: QED



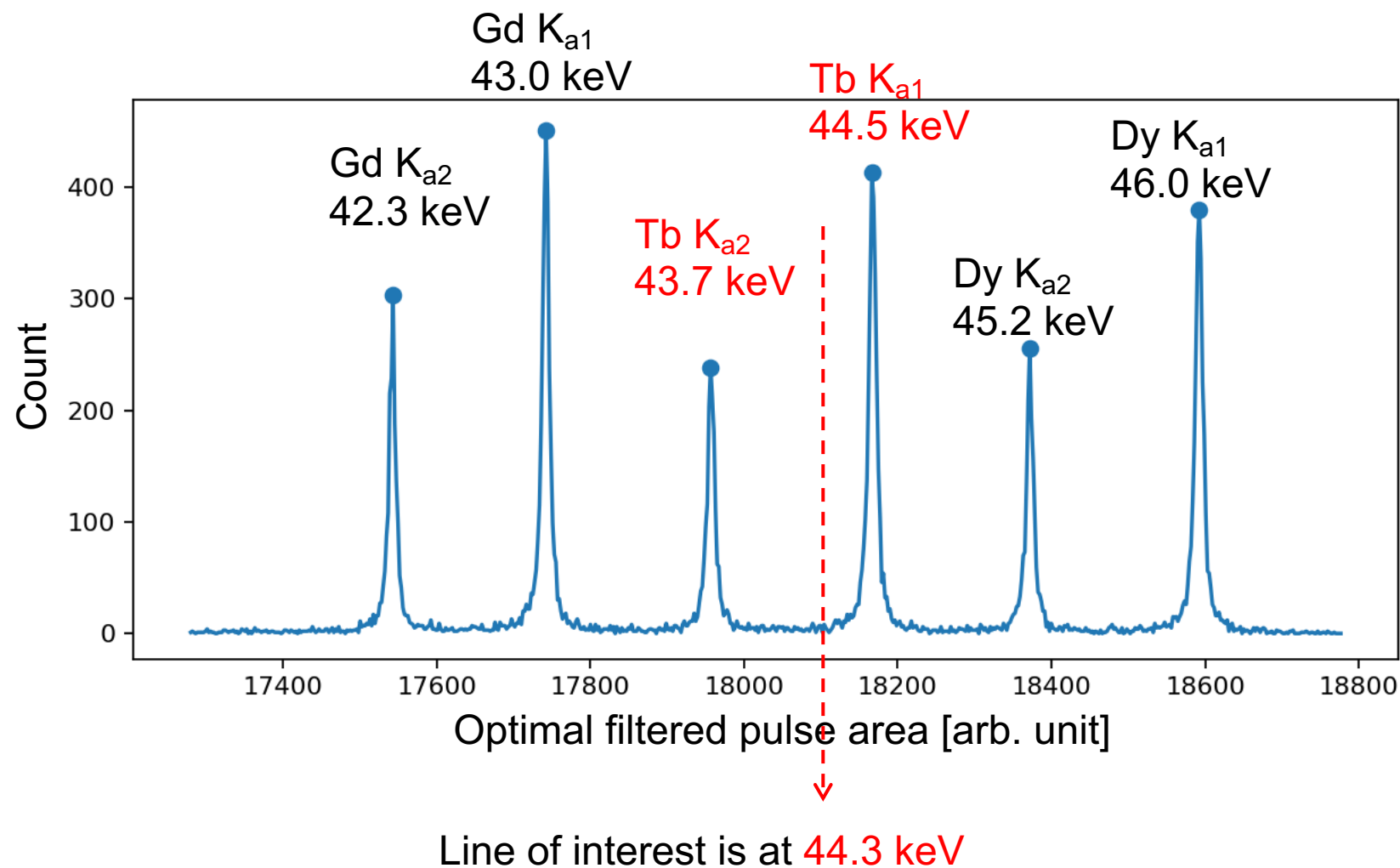
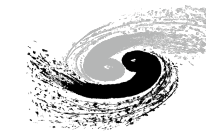
Application II: QED

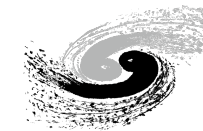


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



Experiment conducted at Beamline-1BM-C, Advanced Photon Source, ANL, USA



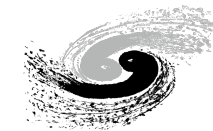


Energy deviation (eV)	Tb $K\alpha_1$ 44.5 keV	Tb $K\alpha_2$ 43.7 keV
5 pJ/K	2.11 (116)	1.00 (122)
6 pJ/K	0.38 (76)	0.13 (84)
7 pJ/K	0.01 (103)	0.24 (107)

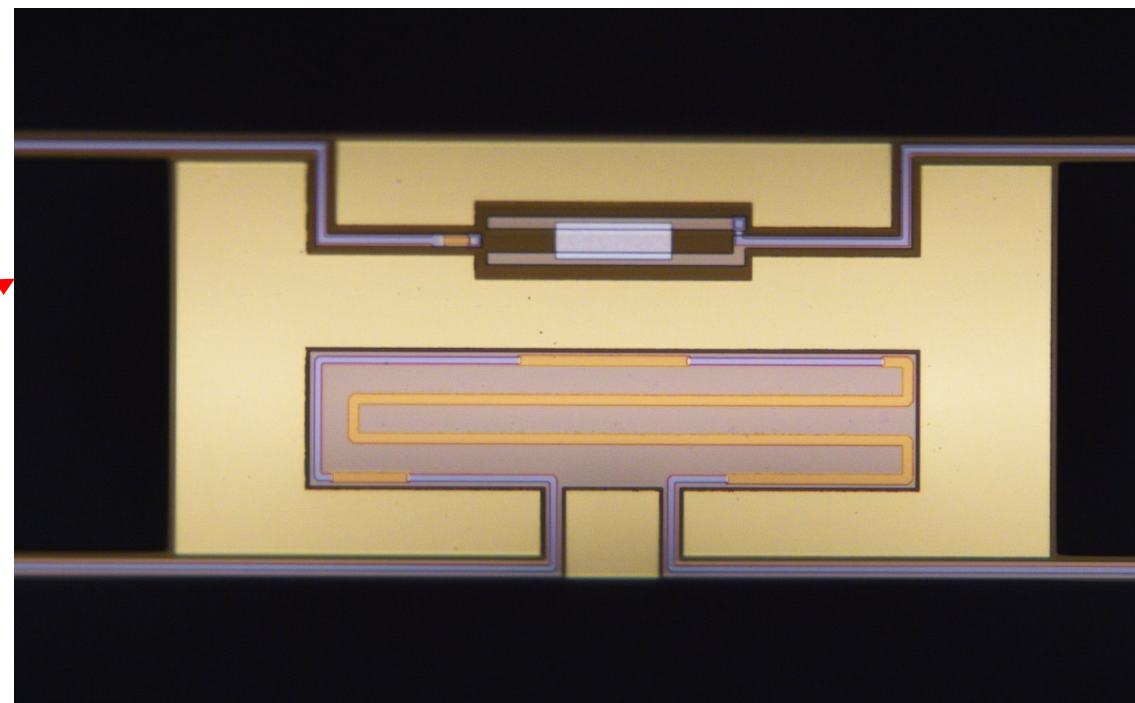
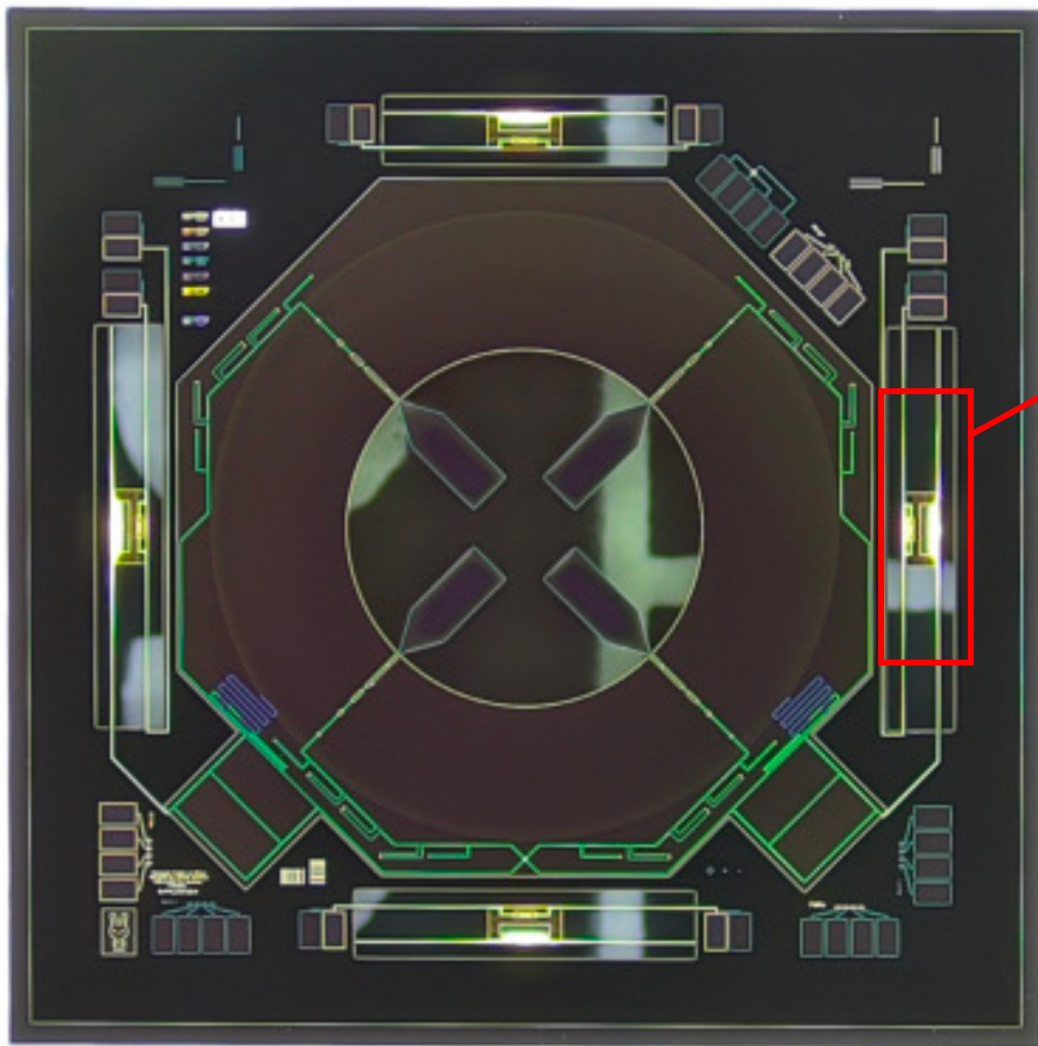
Daikang Yan *et al.* (2022)

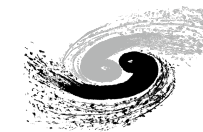
More results to come in 2024.....

Application III: Cosmology

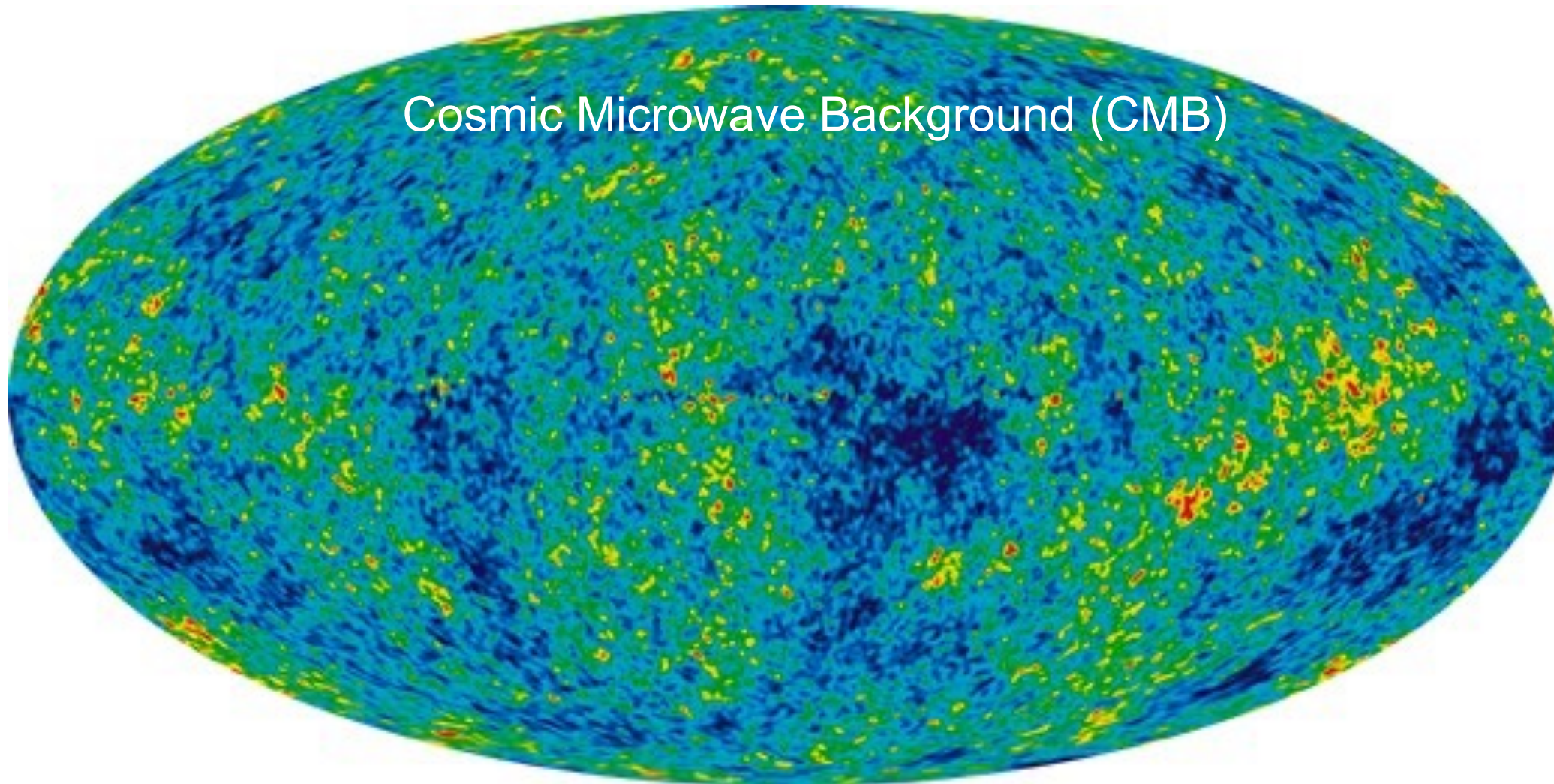


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



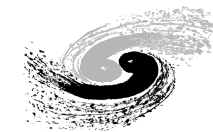


Cosmic Microwave Background (CMB)

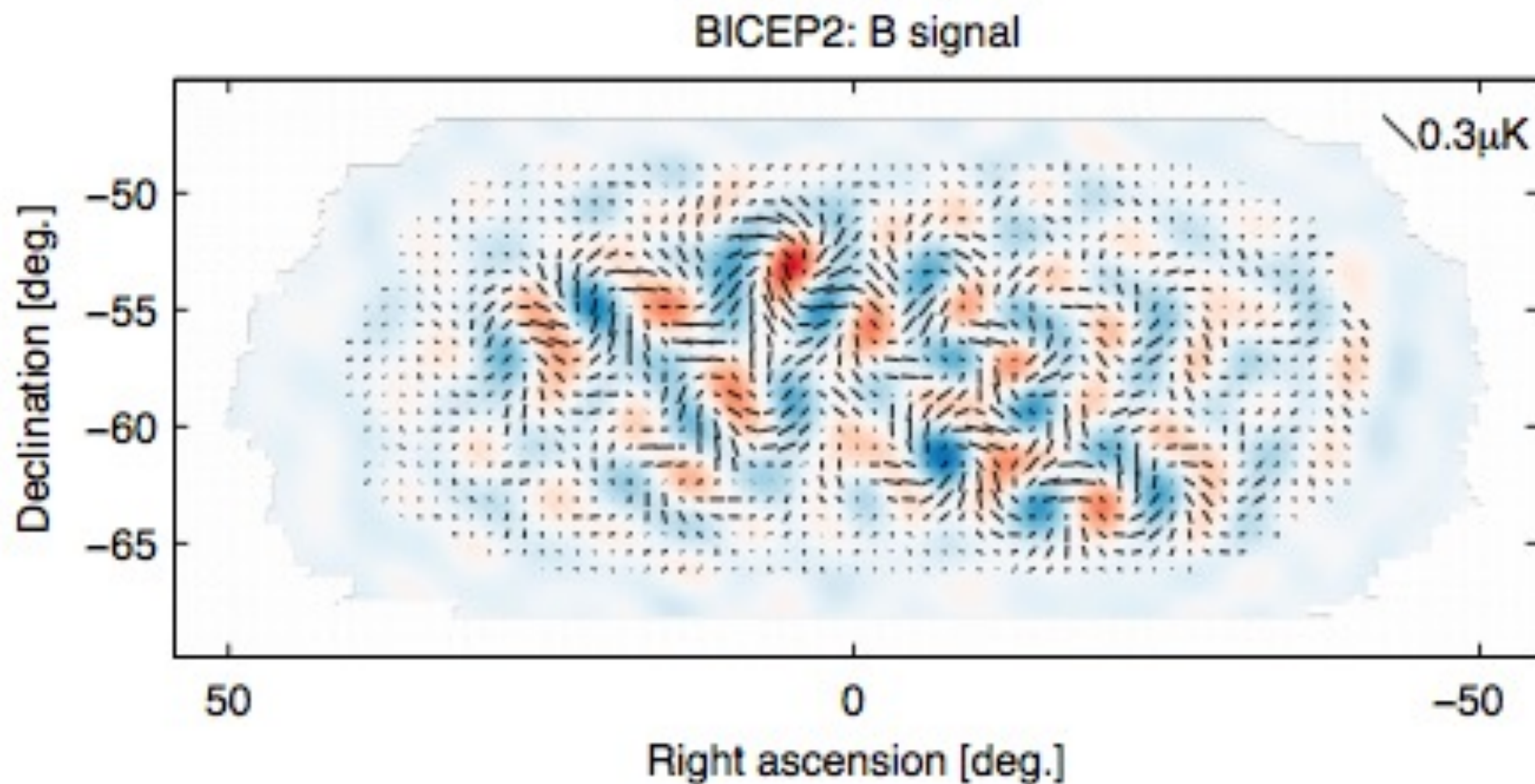


Picture credit: Herbert Huffner, "The Beginning of the World We Know"

Application III: Cosmology

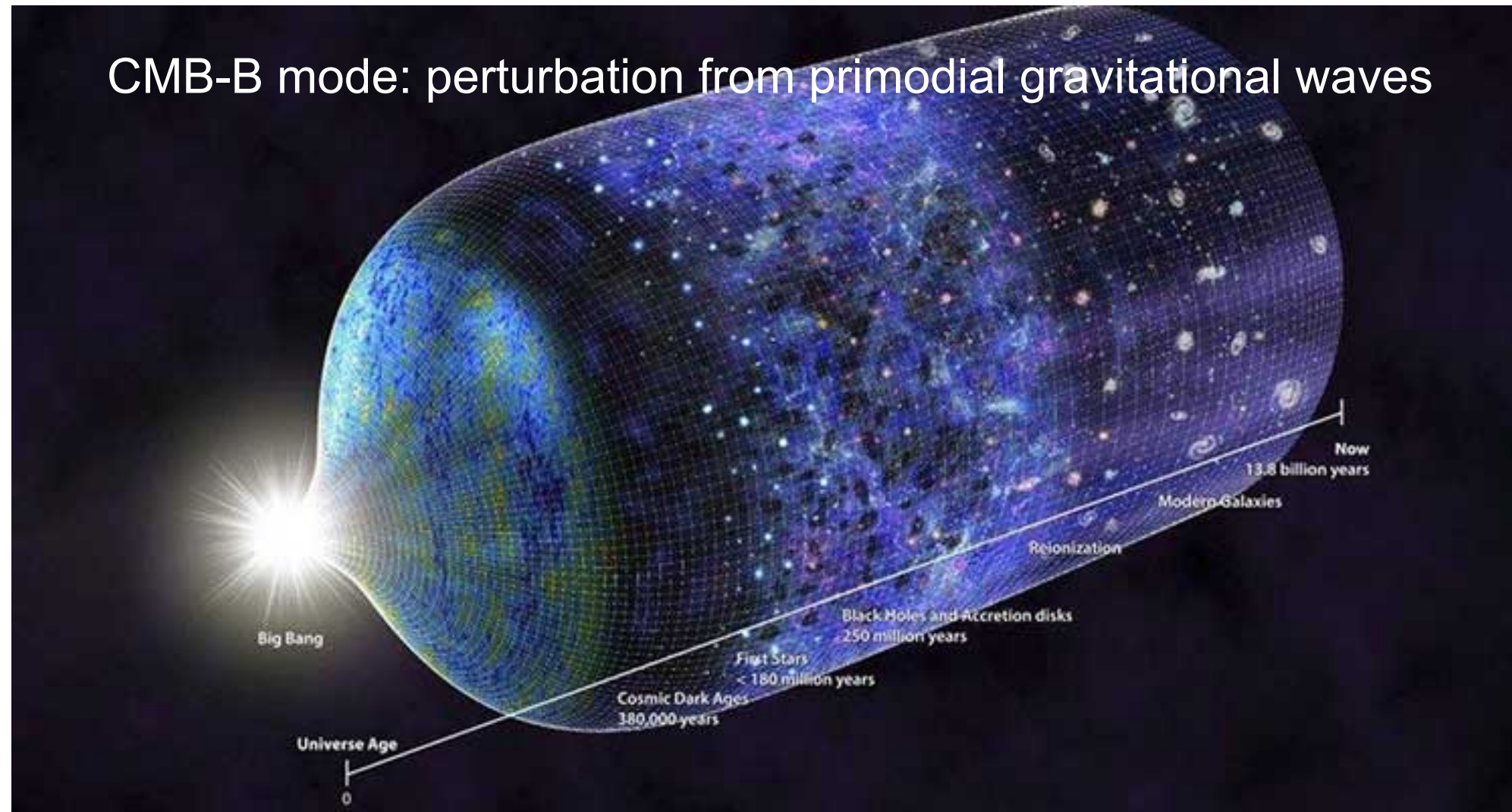


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



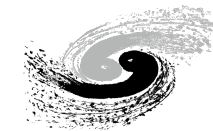
Picture credit: Victor Marin Felip, "The Search for Cosmic Inflation"

Application III: Cosmology

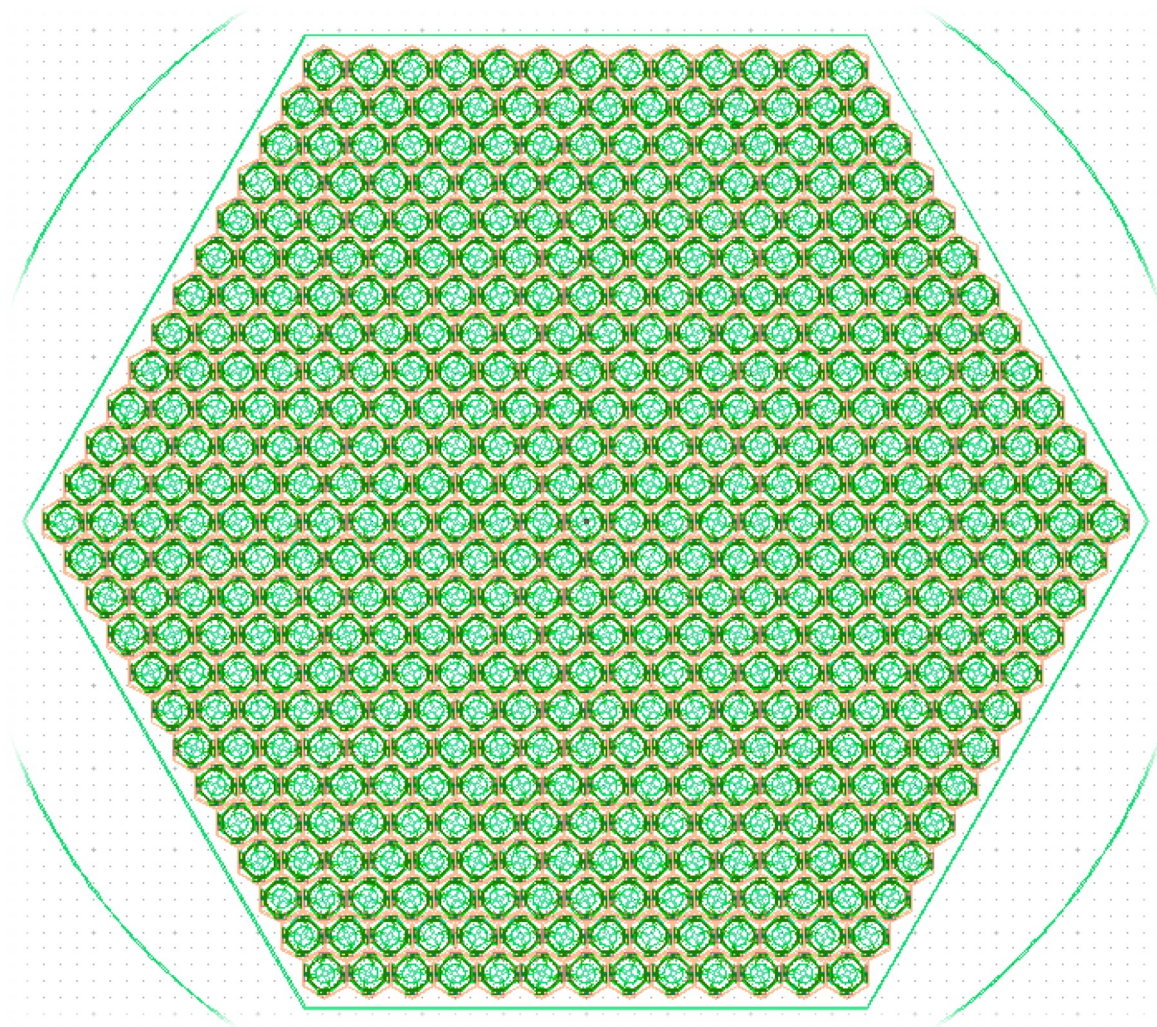


Picture credit: Herbert Huffner, "The Beginning of the World We Know"

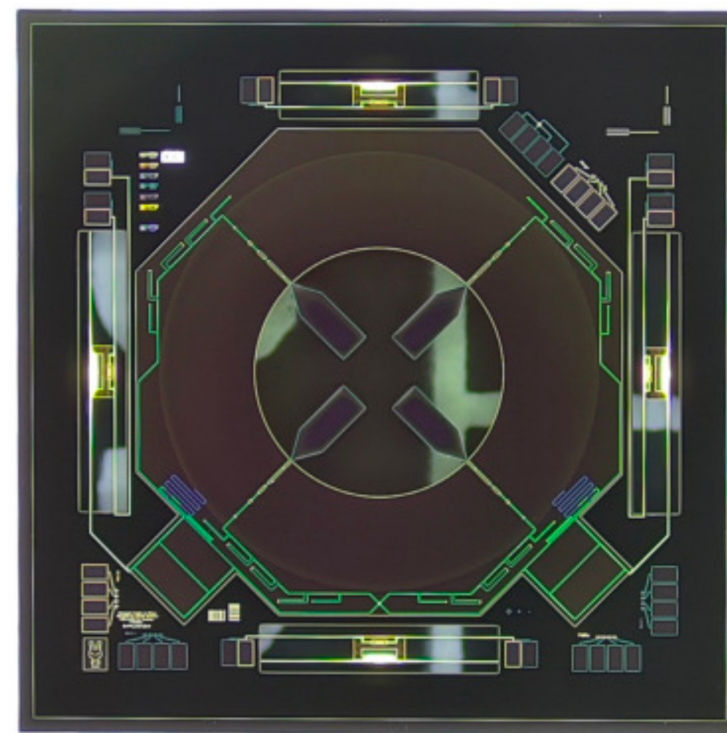
Application III: Cosmology



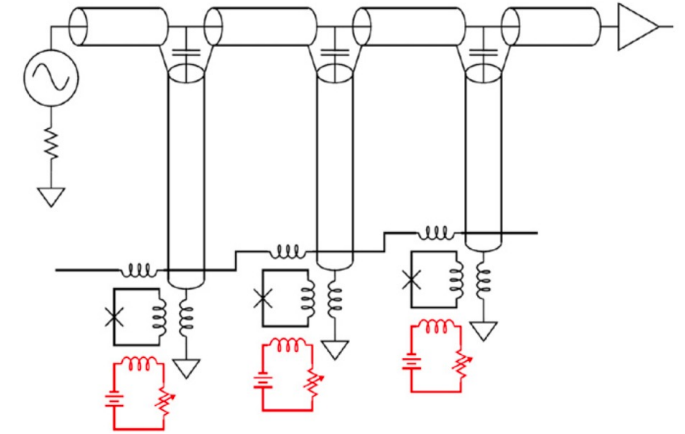
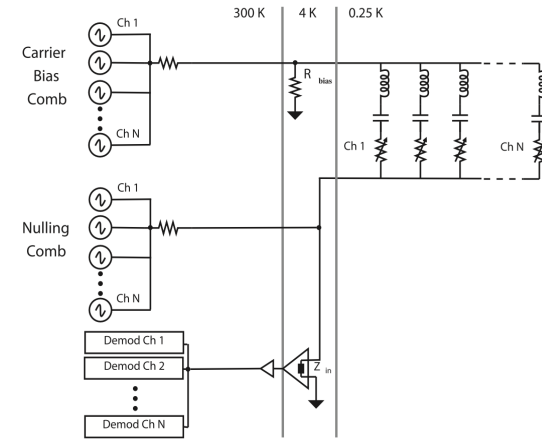
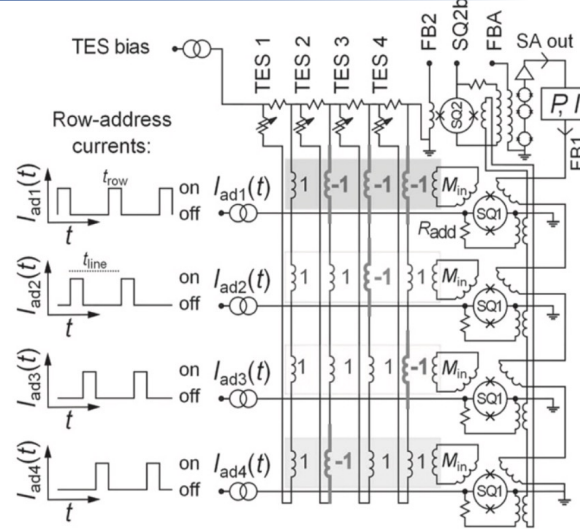
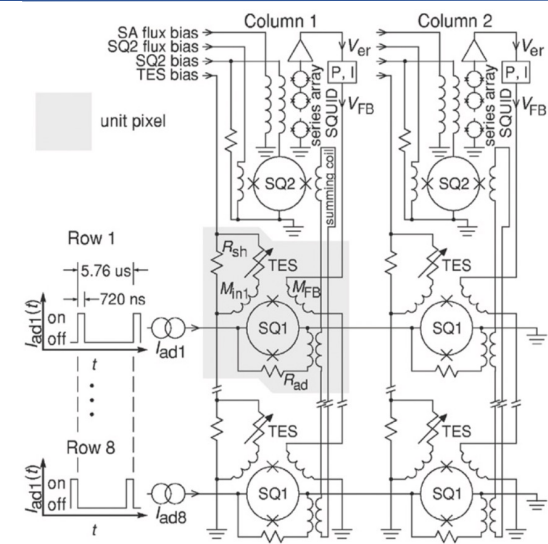
中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



6-inch wafer
432 pixels per array
4 TESs per pixel

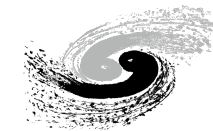


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

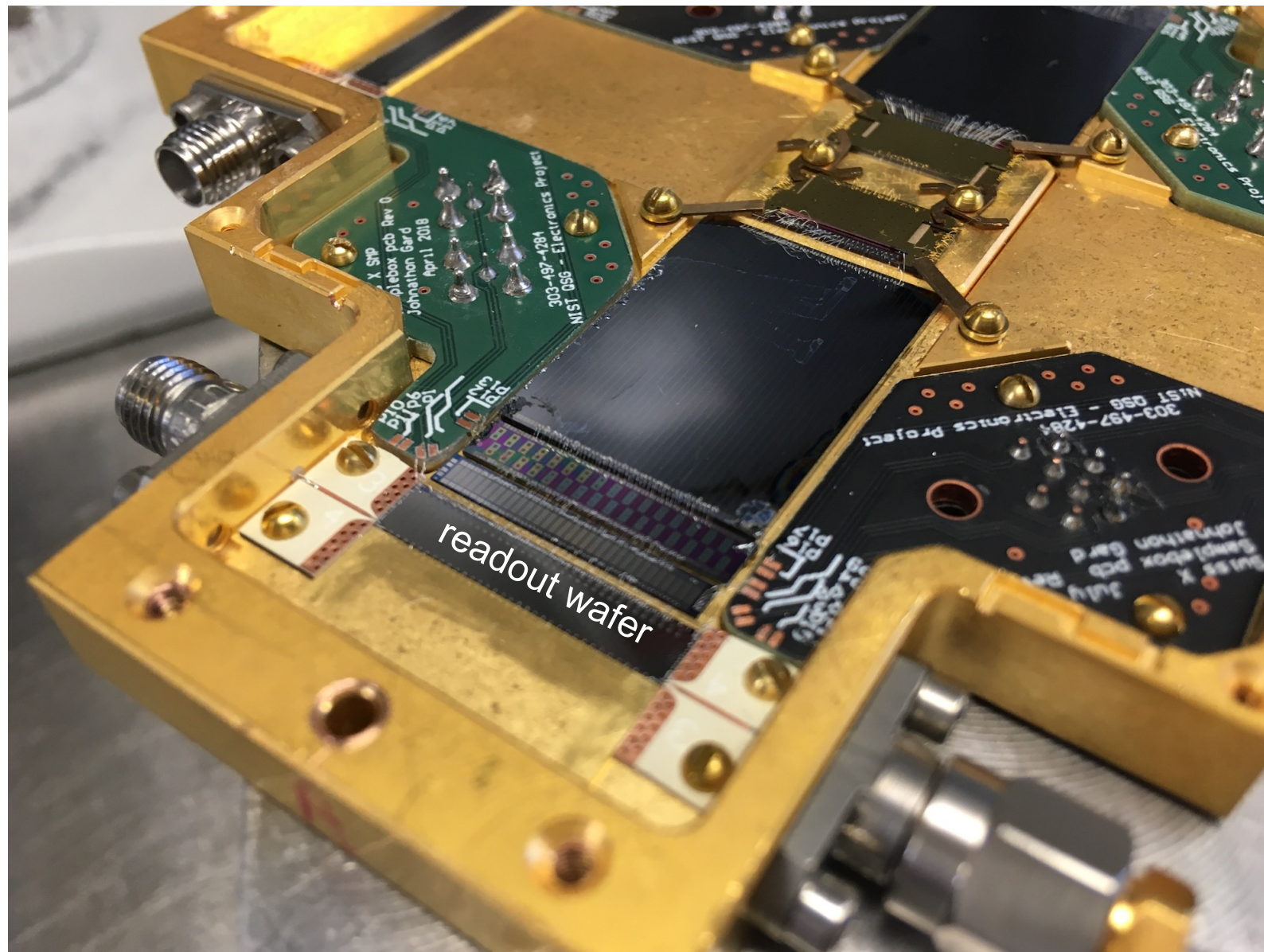
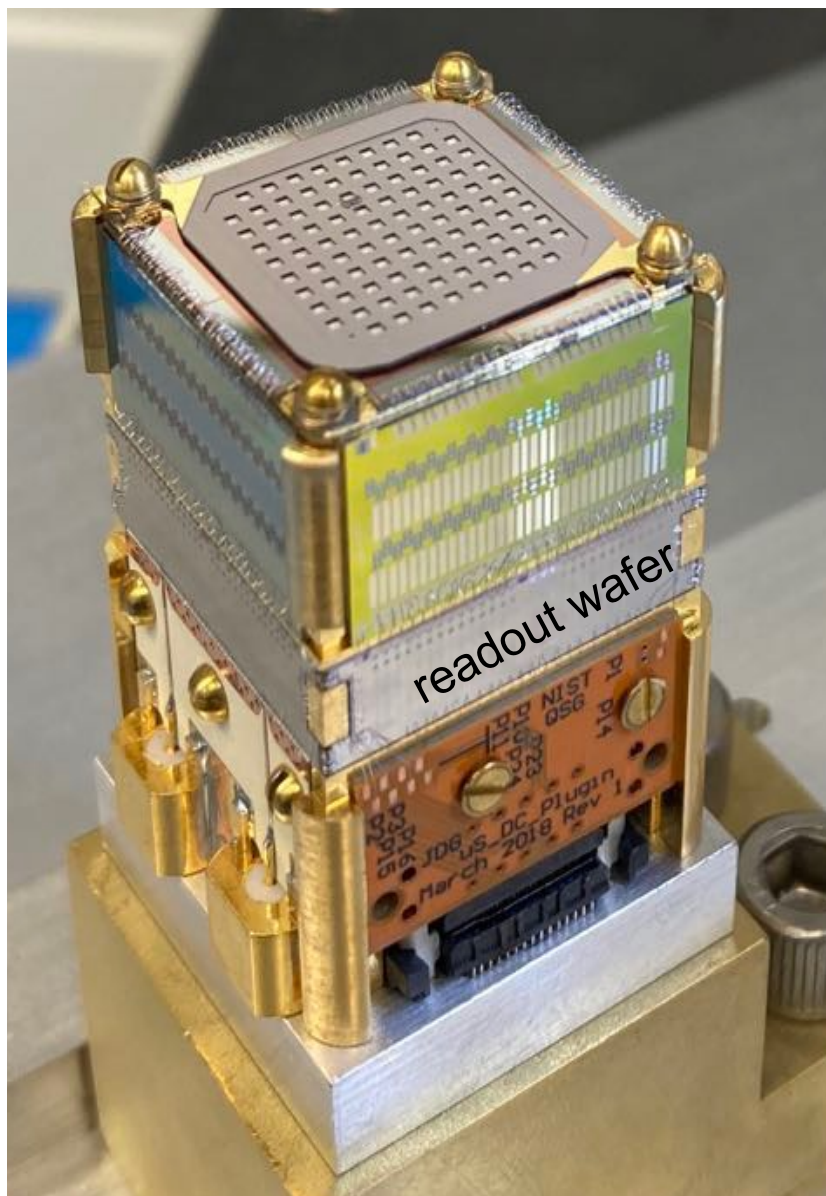


	time-division multiplexing	code-division multiplexing	frequency-division multiplexing	microwave-squid multiplexing
Machanism	pixels in the same column are read out in time series	signals from each pixel are encoded and read out	each pixel is biased in a unique LCR circuit, and detected in a unique frequency channel	TES signal coupled to rf-SQUID, then readout by microwave resonators
Advantage	well-developed technology	each pixel can be biased individually	each pixel can be biased individually	large readout bandwidth, only uses 3 pairs of cables for the whole detector module
Disadvantage	\sqrt{N} sampling noise	one bad pixel kills a whole column	complicated matching between TESs and the readout electronics	pixels are not individually biased, subject to nonuniformity across large arrays

Detector Assembly

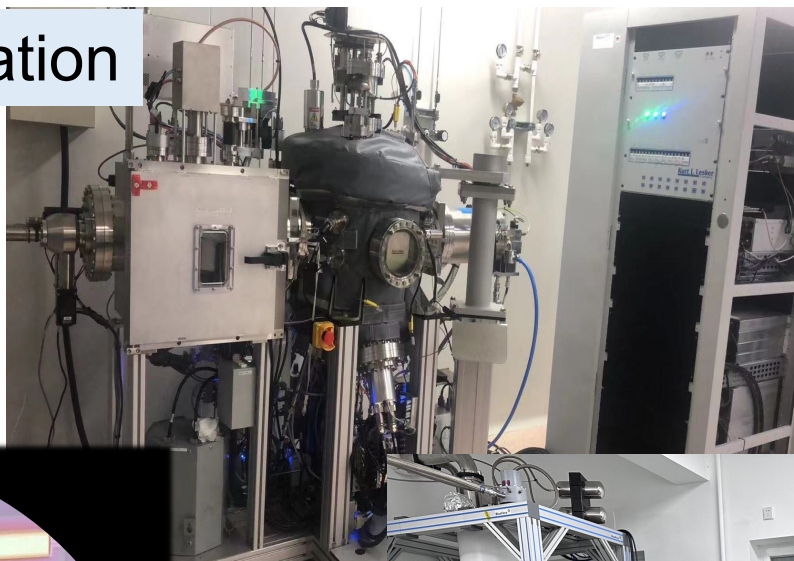


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

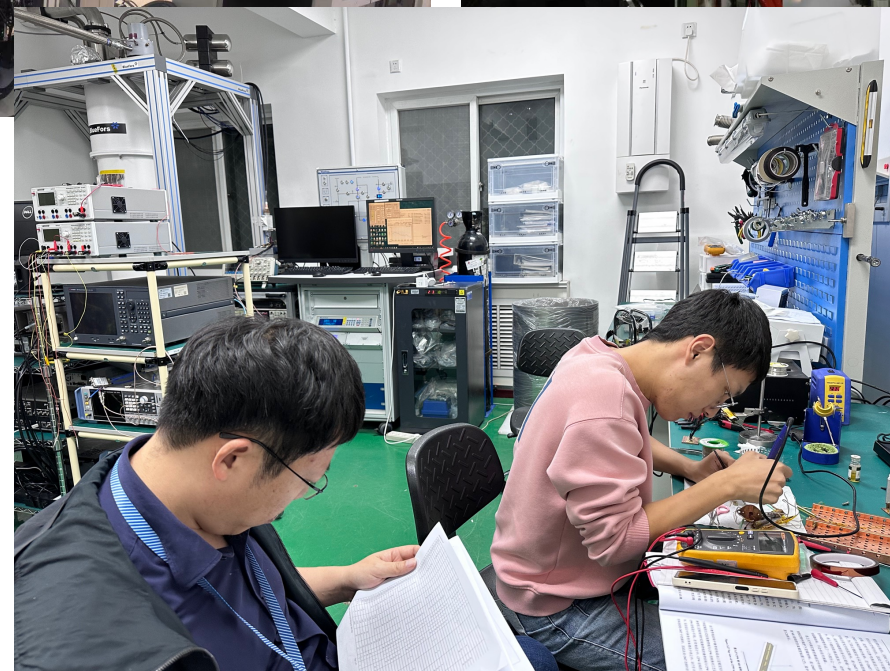
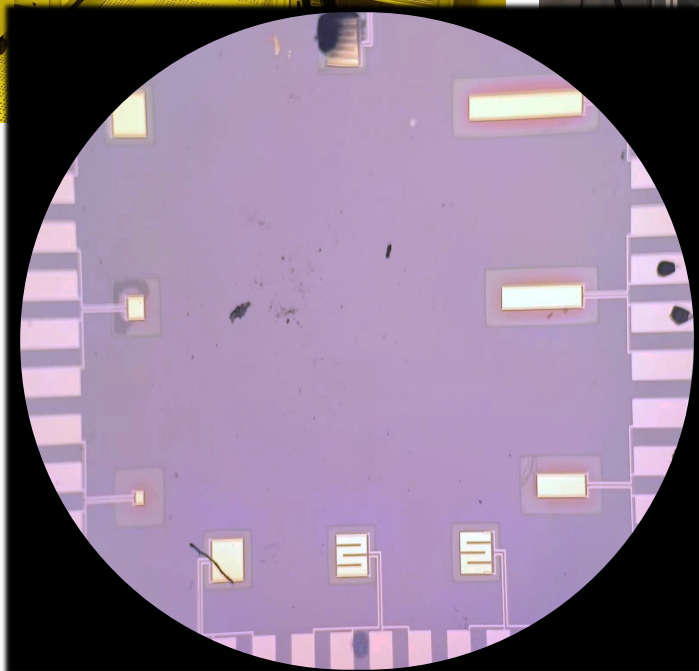


Research at IHEP: R&D

Fabrication

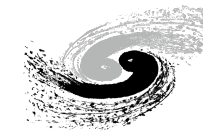


Characterization



What we do:

1. superconductor detector development (mainly TES, and for various applications)
 - overall design
 - device fabrication
 - detector characterization
2. low-temperature multiplexing readout electronics (SQUID)
3. room-temperature detector control & data taking electronics
4. data processing
 - photon signal analysis and optimization



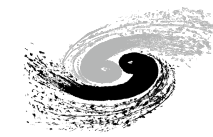
What we do:

1. superconductor detector development (mainly TES, and for various applications)
 - overall design
 - device fabrication
 - detector characterization
2. low-temperature multiplexing readout electronics (SQUID)
3. room-temperature detector control & data taking electronics
4. data processing
 - photon signal analysis and optimization

We are looking for postdocs and students!

Daikang Yan (闫代康): yandk@ihep.ac.cn, yandaikang@gmail.com

Research at IHEP: Life

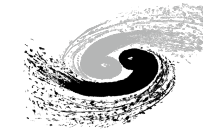


中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences



Daikang Yan - IHEP

Research at IHEP: Life



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

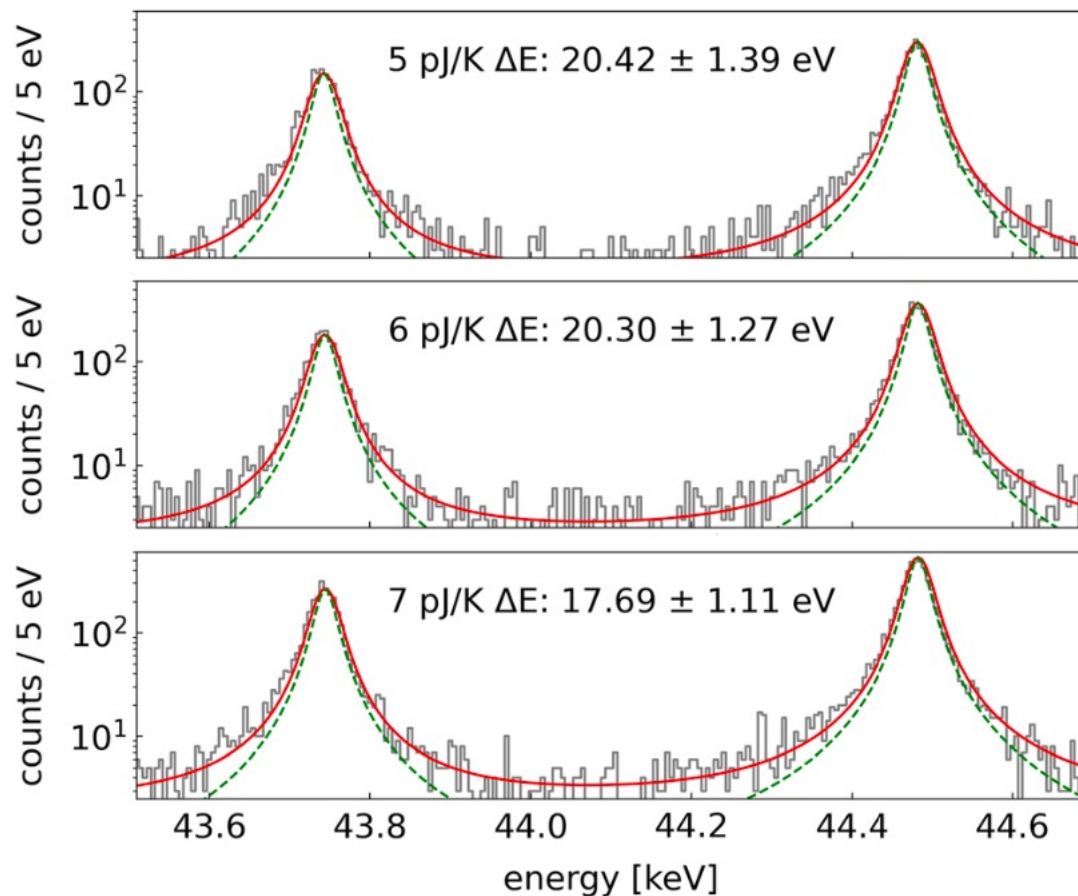
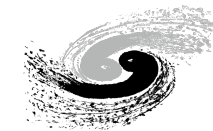


Visit our superconductor device lab,
start your low-resistance journey!



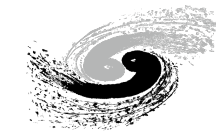
We are looking for postdocs and students!

Daikang Yan (闫代康): yandk@ihep.ac.cn, yandaikang@gmail.com



More results to come in 2024.....

Application II: QED



中国科学院高能物理研究所
Institute of High Energy Physics, Chinese Academy of Sciences

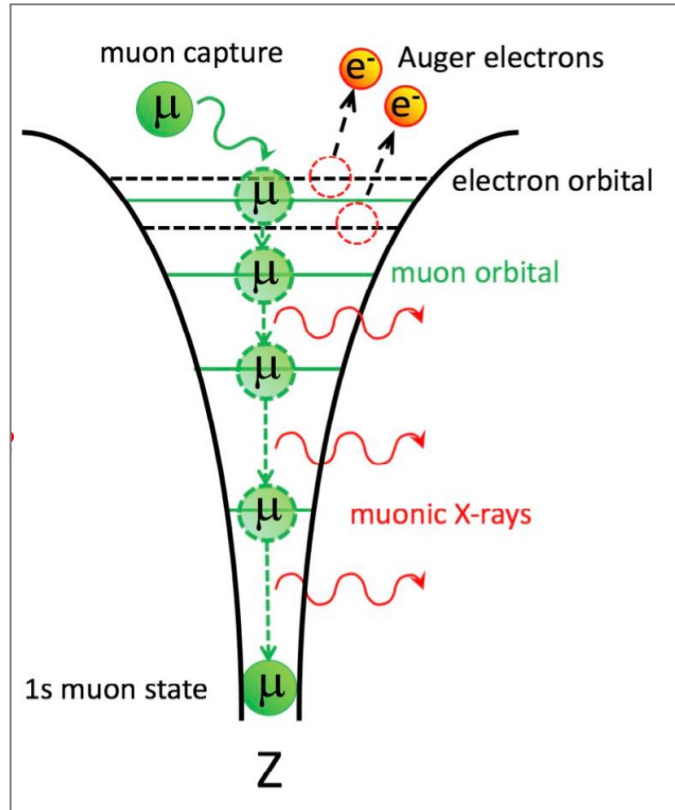
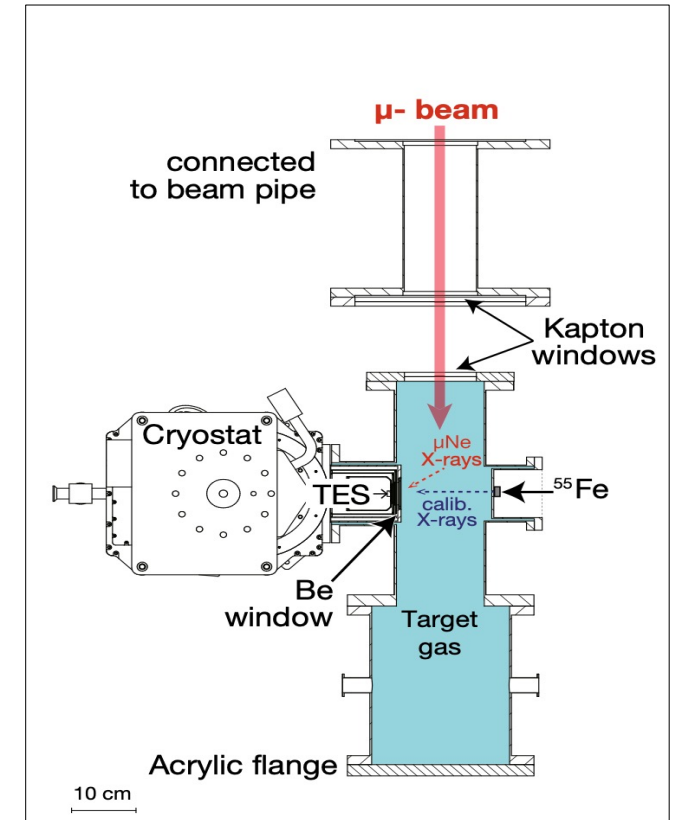


Figure credit: T. Okumura, RIKEN

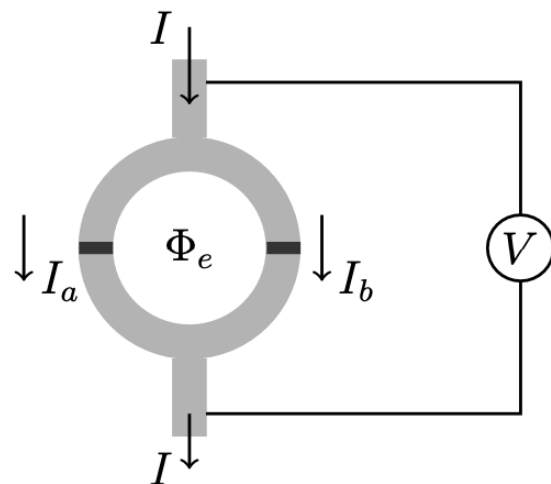
Limitation/Requirement:

- 1) target atom low density
- 2) high energy resolution



S. Okada *et al.*, Journal of Low Temperature Physics (2020) 200:445–451

DC-SQUID



RF-SQUID

